II

(Actos cuya publicación no es una condición para su aplicabilidad)

CONSEJO

DECISIÓN DEL CONSEJO

de 24 de marzo de 1997 [1]

relativa a la eliminación de los derechos relativos a los productos de tecnología de la información

(97/359/CE)

EL CONSEJO DE LA UNIÓN EUROPEA,

Visto el Tratado constitutivo de la Comunidad Europea y, en particular, su artículo 113, en relación con la primera frase del apartado 2 de su artículo 228,

Vista la propuesta de la Comisión,

Considerando que en la nueva Agenda transatlántica adoptada en la cumbre de Madrid de 13 de diciembre de 1995 entre la Unión Europea y Estados Unidos se decidió tratar de celebrar un Acuerdo sobre tecnología de la información;

Considerando que, como consecuencia de los informes de la Comisión acerca de sus consultas exploratorias con países terceros, el 16 de noviembre de 1996 el Consejo decidió iniciar negociaciones con países terceros con objecto de celebrar un Acuerdo sobre tecnología de la información;

Considerando que el 13 de diciembre de 1996 en la primera Conferencia de la Organización Mundial del Comercio celebrada en Singapur la Comunidad Europea aprobó una Declaración ministerial sobre el comercio de productos de tecnología de la información; que esta Declaración establece ciertas condiciones previas para la eliminación de los aranceles realtivos a los productos de tecnología de la información; que se han cumplido estas condiciones previas;

Considerando que la Declaración ministerial sobre el comercio de productos de tecnología de la información junto con sus Anexos y anejos forman parte del Acuerdo sobre comercio de productos de tecnología de la información;

Considerando que el Programa Comunidad Europea-Acuerdo sobre productos de tecnología de la información CXL, que modifica el Programa comunitario existente debería ser sometido a la Organización Mundial del Comercio;

Considerando que el Acuerdo sobre productos de tecnología de la información junto con la Declaración acerca de su aplicación deberían ser aprobados en nombre de la Comunidad,

DECIDE:

Artículo 1

Queda aprobado en nombre de la Comunidad el Acuerdo sobre el comercio de productos de tecnología de la información junto con la Declaración sobre su aplicación.

El texto del Acuerdo y de la Declaración se adjuntan a la presente Decisión.

Artículo 2

Tal como se establece en el apartado 4 del Anexo de la Declaración, el Consejo:

i) toma nota de que han notificado su aceptación participantes que representan aproximadamente el 90 % del comercio mundial de productos de tecnología de la información; y

ii) aprueba en nombre de la Comunidad las solicitudes de escalonamiento de algunos participantes en el ATI.

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(1) El texto consolidado de esta Decisión incluye las correcciones aprobadas por el Consejo el 14 de mayo de 1997.

Artículo 3

El Consejo autoriza a la Comisión a presentar a la Organización Mundial del Comercio las modificaciones al programa de la Comunidad Europea, tal como se enuncian en el Programa Comunidad Europea-Acuerdo sobre produtos de tecnología de la información CXL.

Artículo 4

Se autoriza al Presidente del Consejo para que designe a la persona facultada para firmar el Acuerdo/Protocolo a fin de obligar a la Comunidad.

Artículo 5

La presente Decisión será publicada en el *Diario Oficial de las Comunidades Europeas*.

Hecho en Bruselas, el 24 de marzo de 1997.

Por el Consejo
El Presidente
H. VAN MIERLO

ACUERDO

sobre el comercio de productos de tecnología de la información

ORGANIZACIÓN MUNDIAL DEL COMERCIO

13 de diciembre de 1996

CONFERENCIA MINISTERIAL

Singapur, 9-13 de diciembre de 1996

DECLARACIÓN MINISTERIAL SOBRE EL COMERCIO DE PRODUCTOS DE TECNOLOGÍA DE LA INFORMACIÓN

Singapur, 13 de diciembre de 1996

LOS MINISTROS,

EN REPRESENTACIÓN de los siguientes miembros de la Organización Munidal del Comercio («OMC») y Estados o territorios aduaneros distintos en proceso de adhesión a la OMC, que han llegado a un acuerdo sobre la expansión del comercio mundial de productos de tecnología de la información, y que representan un porcentaje bastante superior al 80 % del comercio mundial de esos productos («partes»):

Australia
Canadá
Comunidades Europeas
Hong Kong
Islandia
Indonesia
Japón
Corea
Noruega
Territorio Aduanero Distinto de Taiwán, Penghu, Kinmen y Matsu
Singapur
Suiza [1]
Turquía
Estados Unidos

CONSIDERANDO la función clave que desempeña el comercio de productos de tecnología de la información en el desarrollo de las industrias de la información y en la expansión dinámica de la economía mundial,

RECONOCIENDO los objetivos de elevación de los niveles de vida y expansión de la producción y el comercio de mercancías,

DESEOSOS de conseguir la máxima libertad del comercio mundial de productos de tecnología de la información,

DESEOSOS de fomentar el desarrollo tecnológico continuo de la industria de la tecnología de la información en todo el mundo,

CONSCIENTES de la contribución positiva que hace la tecnología de la información al crecimiento económico y al bienestar mundiales,

HABIENDO acordado llevar a efecto los resultados de estas negociaciones que implican concesiones adicionales a las incluidas en las Listas anexas al Protocolo de Marrakech anexo al Acuerdo General sobre Aranceles Aduaneros y Comercio de 1994, y

RECONOCIENDO que los resultados de estas negociaciones implican también algunas concesiones ofrecidas en negociaciones conducentes al establecimiento de Listas anexas al Protocolo de Marrakech,

DECLARAN lo siguiente:

1. El régimen de comercio de cada parte deberá evolucionar de manera que aumenten las oportunidades de acceso a los mercados para los productos de tecnología de la información.

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(1) En nombre de la unión aduanera de Suiza y Liechtenstein.

2. De conformidad con las modalidades establecidas en el Anexo de la presente Declaración, cada parte consolidará y eliminará los derechos de aduana y los demás derechos o cargas de cualquier clase, en el sentido de la letra b) del apartado 1 del artículo II del Acuerdo General sobre Aranceles Aduaneros y Comercio de 1994, con respecto a los siguientes productos:

a) todos los productos clasificados (o clasificables) en las partidas del sistema armonizado de 1996 («SA») enumeradas en el apéndice A del Anexo de la presente Declaración; y

b) todos los productos especificados en le apéndice B del Anexo de la presente Declaración, estén o no incluidos en el apéndice A;

mediante reducciones iguales de los tipos de los derechos de aduana a partir de 1997 y hasta 2000, reconociendo que, en limitadas circunstancias, podría ser necesario ampliar el escalonamiento de las reducciones y, antes de la aplicación, los productos comprendidos.

3. Los ministros manifiestan su satisfacción por el gran número de productos comprendidos que figuran en los apéndices del Anexo de la presente Declaración. Encomiendan a funcionarios de sus gobiernos respectivos que hagan esfuerzos de buena fe para finalizar las conversaciones técnicas plurilaterales que se celebrarán en Ginebra sobre la base de esas modalidades y que completen esa tarea no más tarde del 31 de enero de 1997, con el fin de conseguir que la presente Declaración sea aplicada por el mayor número posible de participantes.

4. Los ministros invitan a los ministros de los demás miembros de la OMC y de los Estados o territorios aduaneros distintos en proceso de adhesión a la OMC a que impartan instrucciones análogas a funcionarios de sus gobiernos respectivos, con el fin de que puedan tomar parte en las conversaciones técnicas a que se hace referencia en el apartado 3 *supra* y participar plenamente en la expansión del comercio mundial de productos de tecnología de la información.

Anexo: Modalidades y productos comprendidos

Apéndice A: Lista de partidas del SA

Apéndice B: Lista de productos

ANEXO

MODALIDADES Y PRODUCTOS COMPRENDIDOS

Todo miembro de la Organización Mundial del Comercio, o Estado o territorio aduanero distinto en proceso de adhesión a la OMC, podrá participar en la expansión del comercio mundial de productos de tecnología de la información de conformidad con las modalidades siguientes:

1. Cada participante incorporará las medidas descritas en el apartado 2 de la Declaración a su lista anexa al Acuerdo General sobre Aranceles Aduaneros y Comercio de 1994 y, además, a nivel de línea arancelaria de su arancel o a nivel de 6 dígitos del sistema armonizado de 1996 («SA»), a su arancel oficial o a cualquier otra versión publicada del arancel de aduanas, si fuera esa otra la utilizada comúnmente por los importadores y los exportadores. Cada uno de los participantes que no sea miembro de la OMC aplicará estas medidas de manera autónoma, en espera de la culminación de su adhesión a la OMC, y las incorporará a su lista sobre acceso a los mercados para las mercancías, anexa al Acuerdo sobre la OMC.

2. A estos efectos, cada participante proporcionará a los demás participantes lo antes posible, y en todo caso el 1 de marzo de 1997 a más tardar, un documento que contenga, a) los pormenores sobre cómo preverá el trato arancelario adecuado en su lista de concesiones anexa al Acuerdo sobre la OMC, y b) una lista de las partidas detalladas del SA a las que correspondan los productos especificados en el apéndice B. Estos documentos se examinarán y se aprobarán por consenso, y el proceso de examen se terminará el 1 de abril de 1997 a más tardar. En cuanto haya terminado este proceso de examen de cualquiera de esos documentos, ese documento se presentará como modificación de la Lista del participante de que se trate, de conformidad con la Decisión de 26 de marzo de 1980 sobre procedimientos para la modificación o rectificación de las listas de concesiones arancelarias (IBDD 27S/25).

   a) Las concesiones que debe proponer cada participante como modificaciones de su Lista consolidarán y eliminarán, de la forma que a continuación se indica, todos los derechos de aduana y los demás derechos o cargas de cualquier clase aplicados a los productos de tecnología de la información:

      i) la eliminación de dichos derechos de aduana se llevará a cabo mediante reducciones en tramos iguales de los tipos, a no ser que los participantes acuerden lo contrario. Salvo acuerdo en contrario de los participantes, cada participante consolidará a más tardar todos los aranceles aplicados a los productos enumerados en los apéndices el 1 de julio de 1997 y hará efectiva a más tardar la primera de esas reducciones de los tipos el 1 de julio de 1997, la segunda el 1 de enero de 1998 y la tercera el 1 de enero de 1999, y la eliminación de los derechos de aduana quedará completada el 1 de enero de 2000 a más tardar. Los participantes acuerdan alentar la eliminación autónoma de los derechos de aduana antes de las fechas indicadas. En cade fase, el tipo reducido deberá redondearse al primer decimal; y

      ii) la eliminación de los demás derechos y cargas de cualquier clase citados, en el sentido de la letra b) del apartado 1 del artículo II del Acuerdo General, quedará completada el 1 de julio de 1997, a no ser que en el documento facilitado por el participante a los demás participantes para su examen se indique lo contrario.

   b) Las modificaciones de su Lista que debe proponer un participante para llevar a cabo la consolidación y eliminación de los derechos de aduana aplicados a los productos de tecnología de la información tendrán ese resultado:

      i) en el caso de las partidas del SA que se indican en el apéndice A, mediante la creación, cuando proceda, de subdivisiones en la Lista de ese participante a nivel de línea arancelaria de su arancel nacional; y

      ii) en el caso de los productos especificados en el apéndice B, mediante la adición a la Lista de ese participante de un anexo en el que estarán incluidos todos los productos del apéndice B, en el que han de especificarse las partidas detalladas del SA correspondientes a dichos productos a nivel de línea arancelaria de su arancel nacional o de 6 dígitos del SA.

   Cada participante modificará inmediatamente su arancel nacional de aduanas para recoger en él las modificaciones que haya propuesto, tan pronto com éstas hayan comenzado a surtir efecto.

3. Los participantes se reunirán periódicamente bajo los auspicios del Consejo del comercio de mercancías a fin de examinar los productos comprendidos que se especifican en los apéndices, con miras a acordar por consenso si, a la luz de la evolución de la tecnología, la experiencia en la aplicación de las concesiones arancelarias o los cambios de la nomenclatura del SA, deberán modificarse los apéndices para incorporar productos adicionales, y a fin de celebrar consultas sobre los obstáculos no arancelarios al comercio de productos de tecnología de la información. Dichas consultas no afectarán a los derechos y obligaciones dimanantes del Acuerdo sobre la OMC.

4. Los participantes se reunirán tan pronto como sea factible pero en todo caso no más tarde del 1 de abril de 1997 para examinar la situación de las aceptaciones recibidas y evaluar las conclusiones que deban extraerse. Los participantes pondrán en aplicación las medidas previstas en la presente Declaración a condición de que para entonces hayan notificado su aceptación participantes que representen aproximadamente el 90 % del comercio mundial (1) de productos de tecnología de la información, y a condición de que se haya acordado el escalonamiento a satisfacción de los participantes. Para determinar si se han de poner en aplicación las medidas previstas en la Declaración, en el caso de que el porcentaje del comercio mundial representado por los participantes sea algo inferior al 90 % del comercio mundial de productos de tecnología de la información los participantes podrán tener en cuenta el grado de participación de los Estados o territorios aduaneros distintos que representen para ellos el volumen sustancial de su propio comercio de dichos productos. En esa reunión los participantes comprobarán si se han cumplido estos criterios.

5. Los participantes se reunirán cuantas veces sea necesario y en todo caso el 30 de septiembre de 1997 a más tardar para examinar las discrepancias que puedan existir entre ellos en lo que respecta a la clasificación de los productos de tecnología de la información, comenzando por los productos especificados en el apéndice B. Los participantes se fijan el objetivo común de establecer, en su caso, una clasificación común para esos productos dentro de la nomenclatura actual del SA, tomando en consideración las interpretaciones y decisiones del Consejo de cooperación aduanera (conocido también como Organización Mundial de Aduanas, «OMA»). En caso de que persista una discrepancia en cuanto a la clasificación, los participantes examinarán la posibilidad de hacer una propuesta conjunta a la OMA con respecto a la actualización de la nomenclatura existente del SA o a la solución de la discrepancia en la interpretación de la nomenclatura del SA.

6. Los participantes entienden que el artículo XXIII del Acuerdo General será aplicable a la anulación o menoscabo de ventajas resultantes directa o indirectamente para un miembro de la OMC de la aplicación de la presente Declaración como consecuencia de la aplicación de cualquier medida por otro miembro de la OMC participante, esté o no dicha medida en conflicto con las disposiciones del Acuerdo General.

7. Cada participante examinará con comprensión cualquier solicitud de celebración de consultas que formule otro participante con respecto a los compromisos enunciados *supra*. Dichas consultas se entenderán sin perjuicio de los derechos y obligaciones dimanantes del Acuerdo sobre la OMC.

8. Los participantes, actuando bajo los auspicios del Consejo del comercio de mercancías, informarán de las presentes modalidades a los demás miembros de la OMC y a los Estados o territorios aduaneros distintos en proceso de adhesión a la OMC y entablarán consultas con miras a facilitar su participación en la expansión del comercio de productos de tecnología de la información sobre la base de la presente Declaración.

9. En las presentes modalidades se entenderá por «participante» todo miembro de la OMC, o todo Estado o territorio aduanero distinto en proceso de adhesión a la OMC, que el 1 de marzo de 1997 a más tardar haya proporcionado el documento descrito en el apartado 2.

10. El presente Anexo estará abierto a la aceptación de todos los miembros de la OMC y de cualquier Estado o territorio aduanero distinto en proceso de adhesión a la OMC. Las aceptaciones se notificarán por escrito al director general, quien las comunicará a todos los participantes.

There are two Attachments to the Annex.

Attachment A lists the HS headings or parts thereof to be covered.

Attachment B lists specific products to be covered by an ITA wherever they are classified in the HS.

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(1) Este porcentaje será calculado por la secretaría de la OMC sobre la base de los datos más recientes de que se disponga en el momento de la reunión.

Attachment A, Section 1

HS 96	HS description
3818	Chemical elements doped for use in electronics, in form of discs, wafers or similar forms; chemical compounds doped for use in electronics
8469 11	Word processing machines
8470	Calculating machines and pocket-size data recording, reproducing and displaying machines with a calculating function; accounting machines, postage franking machines, ticket-issuing machines and similar machines, incorporating a calculating device; cash registers:
8470 10	Electronic calculators capable of operating without an external source of electric power and pocket size data recording, reproducing and displaying machines with calculating functions
8470 21	Other electronic calculating machines incorporating a printing device
8470 29	Other
8470 30	Other calculating machines
8470 40	Accounting machines
8470 50	Cash registers
8470 90	Other
8471	Automatic data processing machines and units thereof; magnetic or optical readers, machines for transcribing data onto data media in coded form and machines for processing such data, not elsewhere specified or included:
8471 10	Analogue or hybrid automatic data processing machines
8471 30	Portable digital automatic data processing machines, weighing no more than 10 kg, consisting of at least a central processing unit, a keyboard and a display
8471 41	Other digital automatic data processing machines comprising in the same housing at least a central processing unit and an input and output unit, whether or not combined
8471 49	Other digital automatic data processing machines presented in the form of systems
8471 50	Digital processing units other than those of subheading 8471 41 and 8471 49, whether or not containing in the same housing one or two of the following types of units: storage units, input units, output units
8471 60	Input or output units, whether or not containing storage units in the same housing
8471 70	Storage units, including central storage units, optical disk storage units, hard disk drives and magnetic tape storage units
8471 80	Other units of automatic data processing machines
8471 90	Other
ex 8472 90	Automatic teller machines
8473 21	Parts and accessories of the machines of heading No 8470 of the electronic calculating machines of subheading 8470 10, 8470 21 and 8470 29
8473 29	Parts and accessories of the machines of heading No 8470 other than the electronic calculating machines of subheading 8470 10, 8470 21 and 8470 29
8473 30	Parts and accessories of the machines of heading No 8471
8473 50	Parts and accessories equally suitable for use with machines of two or more of the headings Nos 8469 to 8472
ex 8504 40	Static converters for automatic data processing machines and units thereof, and telecommunication apparatus
ex 8504 50	Other inductors for power supplies for automatic data processing machines and units thereof, and telecommunication apparatus

HS 96	HS description
8517	Electrical apparatus for line telephony or line telegraphy, including line telephone sets with cordless handsets and telecommunication apparatus for carrier-current line systems or for digital line systems; videophones:
8517 11	Line telephone sets with cordless handsets
8517 19	Other telephone sets and videophones
8517 21	Facsimile machines
8517 22	Teleprinters
8517 30	Telephonic or telegraphic switching apparatus
8517 50	Other apparatus, for carrier-current line systems or for digital line systems
8517 80	Other apparatus including entry-phone systems
8517 90	Parts of apparatus of heading 8517
ex 8518 10	Microphones having a frequency range of 300 Hz to 3,4 KHz with a diameter not exceeding 10 mm and a height not exceeding 3 mm, for telecommunication use
ex 8518 30	Line telephone handsets
ex 8518 29	Loudspeakers, without housing, having a frequency range of 300 Hz to 3,4 KHz with a diameter not exceeding 50 mm, for telecommunication use
8520 20	Telephone answering machines
8523 11	Magnetic tapes of a width not exceeding 4 mm
8523 12	Magnetic tapes of a width exceeding 4 mm but not exceeding 6,5 mm
8523 13	Magnetic tapes of a width exceeding 6,5 mm
8523 20	Magnetic discs
8523 90	Other
8524 31	Discs for laser reading systems for reproducing phenomena other than sound or image
ex 8524 39	Other: — for reproducing representations of instructions, data, sound, and image, recorded in a machine readable binary form, and capable of being manipulated or providing interactivity to a user, by means of an automatic data processing machine
8524 40	Magnetic tapes for reproducing phenomena other than sound or image
8524 91	Media for reproducing phenomena other than sound or image
ex 8424 99	Other: — for reproducing representations of instructions, data, sound, and image, recorded in a machine readable binary form, and capable of being manipulated or providing interactivity to a user, by means of an automatic data processing machine
ex 8525 10	Transmission apparatus other than apparatus for radio-broadcasting or television
8525 20	Transmission apparatus incorporating reception apparatus
ex 8525 40	Digital still image video cameras
ex 8527 90	Portable receivers for calling, alerting or paging
ex 8529 10	Aerials or antennae of a kind used with apparatus for radio-telephony and radio-telegraphy
ex 8529 90	Parts of: transmission apparatus other than apparatus for radio-broadcasting or television transmission apparatus incorporating reception apparatus digital still image video cameras portable receivers for calling, alerting or paging

HS 96	HS description
8531 20	Indicator panels incorporating liquid crystal devices (LCD) or light emitting diodes (LED)
ex 8531 90	Parts of apparatus of subheading 8531 20
8532	Electrical capacitors, fixed, variable or adjustable (pre-set):
8532 10	Fixed capacitors designed for use in 50/60 Hz circuits and having a reactive power handling capacity of not less than 0,5 kvar (power capacitors)
8532 21	Tantalum fixed capacitors
8532 22	Aluminium electrolytic fixed capacitors
8532 23	Ceramic dielectric, single layer fixed capacitors
8532 24	Ceramic dielectric, multilayer fixed capacitors
8532 25	Dielectric fixed capacitors of paper or plastics
8532 29	Other fixed capacitors
8532 30	Variable or adjustable (pre-set) capacitors
8532 90	Parts
8533	Electrical resistors (including rheostats and potentiometers), other than heating resistors:
8533 10	Fixed carbon resistors, composition or film types
8533 21	Other fixed resistors for a power handling capacity not exceeding 20 W
8533 29	Other fixed resistors for a power handling capacity of 20 W or more
8533 31	Wirewound variable resistors, including rheostats and potentiometers, for a power handling capacity not exceeding 20 W
8533 39	Wirewound variable resistors, including rheostats and potentiometers, for a power handling capacity of 20 W or more
8533 40	Other variable resistors, including rheostats and potentiometers
8533 90	Parts
8534	Printed circuits
ex 8536 50	Electronic AC switches consisting of optically coupled input and output circuits (Insulated thyristor AC switches)
ex 8536 50	Electronic switches, including temperature protected electronic switches, consisting of a transistor and a logic chip (chip-on-chip technology) for a voltage not exceeding 1 000 V
ex 8536 50	Electromechanical snap-action switches for a current not exceeding 11 amps
ex 8536 69	Plugs and sockets for co-axial cables and printed circuits
ex 8536 90	Connection and contact elements for wires and cables
8541	Diodes, transistors and similar semiconductor devices; photosensitive semiconductor devices, including photovoltaic cells whether or not assembled in modules or made up into panels; light-emitting diodes; mounted piezo-electric crystals:
8541 10	Diodes, other than photosensitive or light-emitting diodes
8541 21	Transistors, other than photosensitive transistors, with a dissipation rate of less than 1 W
8541 29	Transistors, other than photosensitive transistors, with a dissipation rate of 1 W or more
8541 30	Thyristors, diacs and triacs, other than photosensitive devices
8541 40	Photosensitive semiconductor devices, including photovoltaic cells whether or not assembled in modules or made up into panels; light emitting diodes
8541 50	Other semiconductor devices
8541 60	Mounted piezo-electric crystals
8541 90	Parts

HS 96	HS description
8542	Electronic integrated circuits and microassemblies
8542 12	Cards incorporating an electronic integrated circuit ('smart' cards)
8542 13	Metal oxide semiconductors (MOS technology)
8542 14	Circuits obtained by bipolar technology
8542 19	Other monolithic digital integrated circuits, including circuits obtained by a combination of bipolar and MOS technologies (BIMOS technology)
8542 30	Other monolithic integrated circuits
8542 40	Hybrid integrated circuits
8542 50	Electronic microassemblies
8542 90	Parts
8543 81	Proximity cards and tags
ex 8543 89	Electrical machines with translation or dictionary functions
ex 8544 41	Other electric conductors, for a voltage not exceeding 80 V, fitted with connectors, of a kind used for telecommunications
ex 8544 49	Other electric conductors, for a voltage not exceeding 80 V, not fitted with connectors, of a kind used for telecommunications
ex 8544 51	Other electric conductors, for a voltage exceeding 80 V but not exceeding 1 000 V, fitted with connectors, of a kind used for telecommunications
8544 70	Optical fibre cables
9009 11	Electrostatic photocopying apparatus, operating by reproducing the original image directly onto the copy (direct process)
9009 21	Other photocopying apparatus, incorporating an optical system
9009 90	Parts and accessories
9026	Instruments and apparatus for measuring or checking the flow, level, pressure or other variables of liquids or gases (for example, flow meters, level gauges, manometers, heat meters), excluding instruments and apparatus of heading Nos 9014, 9015, 9028 or 9032:
9026 10	Instruments for measuring or checking the flow or level of liquids
9026 20	Instruments and apparatus for measuring or checking pressure
9026 80	Other instruments and apparatus for measuring or checking of heading 9026
9026 90	Parts and accessories of instruments and apparatus of heading 9026
9027 20	Chromatographs and electrophoresis instruments
9027 30	Spectrometers, spectrophotometers and spectrographs using optical radiations (UV, visible, IR)
9027 50	Other instruments and apparatus using optical radiations (UV, visible, IR) of heading No 9027
9027 80	Other instruments and apparatus of heading No 9027 (other than those of heading No 9027 10)
ex 9027 90	Parts and accessories of products of heading 9027, other than for gas or smoke analysis apparatus and microtomes
9030 40	Instruments and apparatus for measuring and checking, specially designed for telecommunications (for example, cross-talk meters, gain measuring instruments, distorsion factor meters, photometers)

Attachment A, Section 2

Semiconductor manufacturing and testing equipment and parts thereof

HS code	Description	Comments
ex 7017 10	Quartz reactor tubes and holders designed for insertion into diffusion and oxidation furnaces for production of semiconductor wafers	For Attachment B
ex 8419 89	Chemical vapor deposition apparatus for semiconductor production	For Attachment B
ex 8419 90	Parts of chemical vapor deposition apparatus for semiconductor production	For Attachment B
ex 8421 19	Spin dryers for semiconductor wafer processing	
ex 8421 91	Parts of spin dryers for semiconductor wafer processing	
ex 8424 89	Deflash machines for cleaning and removing contaminants from the metal leads of semiconductor packages prior to the electroplating process	
ex 8424 89	Spraying appliances for etching, stripping or cleaning semiconductor wafers	
ex 8424 90	Parts of spraying appliances for etching, stripping or cleaning semiconductor wafers	
ex 8456 10	Machines for working any material by removal of material, by laser or other light or photo beam in the production of semiconductor wafers	
ex 8456 91	Apparatus for stripping or cleaning semiconductor wafers	For Attachment B
8456 91	Machines for dry-etching patterns on semiconductor materials	
ex 8456 99	Focused ion beam milling machines to produce or repair masks and reticles for patterns on semiconductor devices	
ex 8456 99	Lasercutters for cutting contacting tracks in semiconductor production by laser beam	For Attachment B
ex 8464 10	Machines for sawing monocrystal semiconductor boules into slices, or wafers into chips	For Attachment B
ex 8464 20	Grinding, polishing and lapping machines for processing of semiconductor wafers	
ex 8464 90	Dicing machines for scribing or scoring semiconductor wafers	
ex 8466 91	Parts for machines for sawing monocrystal semiconductor boules into slices, or wafers into chips	For Attachment B
ex 8466 91	Parts of dicing machines for scribing or scoring semiconductor wafers	For Attachment B
ex 8466 91	Parts of grinding, polishing and lapping machines for processing of semiconductor wafers	
ex 8466 93	Parts of focused ion beam milling machines to produce or repair masks and reticles for patterns on semiconductor devices	
ex 8466 93	Parts of lasercutters for cutting contacting tracks in semiconductor production by laser beam	For Attachment B
ex 8466 93	Parts of machines for working any material by removal of material, by laser or other light or photo beam in the production of semiconductor wafers	
ex 8466 93	Parts of apparatus for stripping or cleaning semiconductor wafers	For Attachment B
ex 8466 93	Parts of machines for dry-etching patterns on semiconductor materials	
ex 8477 10	Encapsulation equipment for assembly of semiconductors	For Attachment B

HS code	Description	Comments
ex 8477 90	Parts of encapsulation equipment	For Attachment B
ex 8479 50	Automated machines for transport, handling and storage of semiconductor wafers, wafer cassettes, wafer boxes and other material for semiconductor devices	For Attachment B
ex 8479 89	Apparatus for growing or pulling monocrystal semiconductor boules	
ex 8479 89	Apparatus for physical deposition by sputtering on semiconductor wafers	For Attachment B
ex 8479 89	Apparatus for wet etching, developing, stripping or cleaning semiconductor wafers and flat panel displays	For Attachment B
ex 8479 89	Die attach apparatus, tape automated bonders, and wire bonders for assembly of semiconductors	For Attachment B
ex 8479 89	Encapsulation equipment for assembly of semiconductors	For Attachment B
ex 8479 89	Epitaxial deposition machines for semiconductor wafers	
ex 8479 89	Machines for bending, folding and straightening semiconductor leads	For Attachment B
ex 8479 89	Physical deposition apparatus for semiconductor production	For Attachment B
ex 8479 89	Spinners for coating photographic emulsions on semiconductor wafers	For Attachment B
ex 8479 90	Part of apparatus for physical deposition by sputtering on semiconductor wafers	For Attachment B
ex 8479 90	Parts for die attach apparatus, tape automated bonders, and wire bonders for assembly of semiconductors	For Attachment B
ex 8479 90	Parts for spinners for coating photographic emulsions on semiconductor wafers	For Attachment B
ex 8479 90	Parts of apparatus for growing or pulling monocrystal semiconductor boules	
ex 8479 90	Parts of apparatus for wet etching, developing, stripping or cleaning semiconductors wafers and flat panel displays	For Attachment B
ex 8479 90	Parts of automated machines for transport, handling and storage for semiconductor wafers, wafer cassettes, wafer boxes and other material for semiconductor devices	For Attachment B
ex 8479 90	Parts of encapsulation equipment for assembly of semiconductors	For Attachment B
ex 8479 90	Parts of epitaxial deposition machines for semiconductor wafers	
ex 8479 90	Parts of machines for bending, folding and straightening semiconductor leads	For Attachment B
ex 8479 90	Parts of physical deposition apparatus for semiconductor production	For Attachment B
ex 8480 71	Injection and compression moulds for the manufacture of semiconductor devices	
ex 8514 10	Resistance heated furnaces and ovens for the manufacture of semiconductor devices on semiconductor wafers	
ex 8514 20	Inductance or dielectric furnaces and ovens for the manufacture of semiconductor devices on semiconductors wafers	
ex 8514 30	Apparatus for rapid heating of semiconductor wafers	For Attachment B
ex 8514 30	Parts of resistance heated furnaces and ovens for the manufacture of semiconductor devices on semiconductor wafers	
ex 8514 90	Parts of apparatus for rapid heating of wafers	For Attachment B
ex 8514 90	Parts of furnaces and ovens of Headings No 8414 10 to No 8514 30	
ex 8536 90	Wafer probers	For Attachment B

HS code	Description	Comments
8543 11	Ion implanters for doping semiconductor materials	
ex 8543 30	Apparatus for wet etching, developing, stripping or cleaning semiconductor wafers and flat panel displays	For Attachment B
ex 8543 90	Parts of apparatus for wet etching, developing, stripping or cleaning semiconductor wafers and flat panel displays	For Attachment B
ex 8543 90	Parts of ion implanters for doping semiconductor materials	
9010 41 to 9010 49	Apparatus for projection, drawing or plating circuit patterns on sensitized semiconductor materials and flat panel displays	
ex 9010 90	Parts and accessories of the apparatus of Headings No 9010 41 to 9010 49	
ex 9011 10	Optical stereoscopic microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	For Attachment B
ex 9011 20	Photomicrographic microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	For Attachment B
ex 9011 90	Parts and accessories of optical stereoscopic microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	For Attachment B
ex 9011 90	Parts and accessories of photomicrographic microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	For Attachment B
ex 9012 10	Electron beam microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	For Attachment B
ex 9012 90	Parts and accessories of electron beam microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	For Attachment B
ex 9017 20	Pattern generating apparatus of a kind used for producing masks or reticles from photoresist coated substrates	For Attachment B
ex 9017 90	Parts and accessories for pattern generating apparatus of a kind used for producing masks or reticles from photoresist coated substrates	For Attachment B
ex 9017 90	Parts of such pattern generating apparatus	For Attachment B
9030 82	Instruments and apparatus for measuring or checking semiconductor wafers or devices	
ex 9030 90	Parts and accessoires of instruments and apparatus for measuring or checking semiconductor wafers or devices	
ex 9030 90	Parts of instruments and appliances for measuring or checking semiconductor wafers or devices	
ex 9031 41	Optical instruments and appliances for inspecting semiconductor wafers or devices or for inspecting masks, photomasks or reticles used in manufacturing semiconductor devices	
ex 9031 49	Optical instruments and appliances for measuring surface particulate contamination on semiconductor wafers	
ex 9031 90	Parts and accessories of optical instruments and appliances for inspecting semiconductor wafers or devices or for inspecting masks, photomasks or reticles used in manufacturing semiconductor devices	
9031 90	Parts and accessories of optical instruments and appliances for measuring surface particulate contamination on semiconductor wafers	

Attachment B

Positive list of specific products to be covered by this agreement wherever they are classified in the HS.

Where parts are specified, they are to be covered in accordance with HS Notes 2 (b) to Section XVI and Chapter 90, respectively.

- Computers: automatic data processing machines capable of (1) storing the processing program or programs and at least the data immediately necessary for the execution of the program; (2) being freely programmed in accordance with the requirements of the user; (3) performing arithmetical computations specified by the user; and (4) executing, without human intervention, a processing program which requires them to modify their execution, by logical decision during the processing run.

  The agreement covers such automatic data processing machines whether or not they are able to receive and process with the assistance of central processing unit telephony signals, television signals, or other analogue or digitally processed audio or video signals. Machines performing a specific function other than data processing, or incorporating or working in conjunction with an automatic data processing machine, and not otherwise specified under Attachment A or B, are not covered by this agreement,

- Electric amplifiers when used as repeaters in line telephony products falling within this agreement, and parts thereof,

- Flat panel displays (including LCD, electro luminescence, plasma and other technologies) for products falling within this agreement, and parts thereof,

- Network equipment: local area network (LAN) and wide area network (WAN) apparatus, including those products dedicated for use solely or principally to permit the interconnection of automatic data processing machines and units thereof for a network that is used primarily for the sharing of resources such as central processor units, data storage devices and input or output — including adapters, hubs, in-line repeaters, converters, concentrators, bridges and routers and printed circuit assemblies for physical incorporation into automatic data processing machines and units thereof,

- Monitors: display units of automatic data processing machines with a cathode ray tube with a dot screen pitch smaller than 0,4 mm not capable of receiving and processing television signals or other analogue or digitally processed audio or video signals without assistance of a central processing unit of a computer as defined in this agreement. The agreement does not, therefore, cover televisions, including high definition televisions (1),

- Optical disc storage units, for automatic data processing machines (including CD drives and DVD-drives), whether or not having the capability of writing/recording as well as reading, whether or not in their own housings,

- Paging alert devices, and parts thereof,

- Plotters whether input or output units of HS heading No 8471 or drawing or drafting machines of HS heading No 9017,

- Printed circuit assemblies for products falling within this agreement, including such assemblies for external connections such as cards that conform to the PCMCIA standard.

  Such printed circuit assemblies consist of one or more printed circuits of heading 8534 with one or more active elements assembled thereon, with or without passive elements 'Active elements' means diodes, transistors, and similar semiconductor devices, whether or not photosensitive, of heading 8541, and integrated circuits and micro assemblies of heading 8542,

- Projection type flat panel display units used with automatic data processing machines which can display digital information generated by the central processing unit,

- Proprietary format storage devices including media therefore for automatic data processing machines, with or without removable media and whether magnetic, optical or other technology, including Bernouilli Box, Syquest, or Zipdrive cartridge storage units,

- Multimedia upgrade kits for automatic data processing machines, and units thereof, put up for retail sale, consisting of, at least, speakers and/or microphones as well as a printed circuit assembly that enables the ADP machines and units thereof to process audio signals (sound cards),

- Set top boxes which have a communication function: a microprocessor-based device incorporating a modem for gaining access to the Internet, and having a function of interactive information exchange.

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(1) Participants will conduct a review of this product description in January 1999 under the consultation provisions of paragraph 3 of the Declaration.

EC — ITA — Schedule CXL

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
3818 00	Chemical elements doped for use in electronics, in the form of discs, wafers or similar forms; chemical compounds doped for use in electronics						
3818 00 10	— Doped silicon	6,9	free	5,2	3,5	1,7	free
3818 00 90	— Other	6,9	free	5,2	3,5	1,7	free
7020 00	Other articles of glass						
7020 00 05	— Quartz reactor tubes and holders designed for insertion into diffusion and oxidation furnaces for production of semiconductor wafers	4	free	3,0	2,0	1,0	free
7020 00 10	— Of fused quartz or other fused silica						
7020 00 30	— Of glass having a linear coefficient of expansion not exceeding 5 × 10-6 per Kelvin within a temperature range of 0 °C to 300 °C						
7020 00 80	— Other						
8419	Machinery, plant or laboratory equipment, whether or not electrically heated, for the treatment of materials by a process involving a change of temperature such as heating, cooking, roasting, destilling, rectifying, sterilizing, pasteurizing, steaming, drying, evaporating, vapourizing, condensing or cooling, other than machinery or plant of a kind used for domestic purposes; instantaneous or storage water heaters, non-electric:						
8419 89	— — Other						
8419 89 10	— — — Cooling towers and similar plant for direct cooling (without a separating wall) by means of recirculated water						
8419 89 15	— — — Apparatus for rapid heating of semiconductor wafers	free	free	free	free	free	free
8419 89 20	— — — Apparatus for chemical vapour deposition on semiconductor wafers	free	free	free	free	free	free
8419 89 25	— — — Apparatus for physical vapour deposition by electronic beam or evaporation on semiconductor wafers	free	free	free	free	free	free
8419 89 30	— — — Vacuum-vapour plant for the deposition of metal						
8419 89 95	— — — Other						
8419 90	— Parts						
8419 90 10	— — — Of heat exchange units, for use in civil aircraft						
8419 90 20	— — Of subheading 8419 20 00						
8419 90 30	— — For apparatus of subheading 8419 89 15 to 8419 89 25	2,7	free	2,0	1,4	0,7	free
8419 90 80	— — Other						
8421	Centrifuges, including centrifugal dryers; filtering or purifying machinery and apparatus, for liquids or gases:						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8421 19	– – Other						
8421 19 10	– – – For use in civil aircraft						
	– – – Other						
8421 19 91	– – – – Centrifuges of a kind used in laboratories						
	– – – – Centrifuges of a kind used in the manufacturing of semiconductors wafers:						
8421 19 93	– – – – – Spinners for coating photographic emulsions on simiconductor wafers	free	free	free	free	free	free
8421 19 95	– – – – – Other	1,5	free	1,1	0,8	0,4	free
8421 19 97	– – – – Other						
	– Parts						
	– – – Of centrifuges, including centrifugal dryers						
8421 91 10	– – – For apparatus of subheading 8421 19 93 or 8421 19 95	2,5	free	1,9	1,3	0,6	free
8421 91 90	– – – Other						
8421 99 00	– – Other						
8424	Mechanical appliances (whether or not hand-operated) for projecting, dispersing or spraying liquids or powders; fire extinguishers, whether or not charged; spray guns and similar appliances; steam or sand blasting machines and similar jet projecting machines:						
8424 89	– – Other						
8424 89 20	– – – Spraying appliances for etching, stripping or cleaning semiconductor waters	free	free	free	free	free	free
8424 89 30	– – – Deflash machines for cleaning and removing contaminants from the metal leads of semiconductor packages prior to the electroplating process	2,8	free	2,1	1,4	0,7	free
8424 89 80	– – – Other						
8424 90	– Parts						
8424 90 10	– – Of apparatus of subheading 8424 89 20	2,8	free	2,1	1,4	0,7	free
8424 90 90	– – Other						
8428	Other lifting, handling, loading or unloading machinery (for example, lifts, escalators, conveyors, teleferics):						
8428 39	– – Other						
8428 39 10	– – – For use in civil aircraft						
	– – – Other						
8428 39 91	– – – – Roller conveyors						
8428 39 93	– – – – Automated material handling machines for transport, handling and storage of semiconductor wafers, wafer cassettes, wafer boxes and other material for semiconductor devices	free	free	free	free	free	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8428 39 98	— — — — Other						
8431	Parts suitable for use solely or principally with the machinery of heading Nos 8425 to 8430:						
8431 39	— — Other						
8431 39 10	— — — Of rolling-mill machinery of subheading 8428 90 30						
8431 39 20	— — — Of machinery of subheading 8428 39 93	1,6	free	1,2	0,8	free	free
8431 39 80	— — — Other						
8456	Machine-tools for working any material by removal of material, by laser or other light or photon beam, ultrasonic, electro-discharge, electro-chemical, electron beam, ionic-beam or plasma arc processes:						
8456 10	— Operated by laser or other light or photon beam processes						
8456 10 10	— — Of a kind used in the manufacturing of semiconductor wafers or devices	4,7	free	3,5	2,4	1,2	free
8456 10 90	— — Other						
8456 91 00	— — For dry-etching patterns on semiconductor materials	free	free	feee	free	free	fee
8456 99	— — Other						
8456 99 10	— — — Focused ion beam milling machines for producing or repairing masks and reticles for patterns on semiconductor devices	free	free	free	free	free	free
8456 99 30	— — — Apparatus for stripping or cleaning semiconductor wafers	free	free	free	free	free	free
8456 99 90	— — — Other						
8462	Machine-tools (including presses) for working metal by forging, hammering or die-stamping; machine-tools (including presses) for working metal by bending, folding, straightening, flattening, shearing, punching or notching; presses for working metal or metal carbides, not specified above:						
	— Bending, folding, straightening or flattening machines (including presses)						
8462 21	— — Numerically controlled						
8462 21 05	— — — Of a kind used in manufacturing semiconductor devices	3,2	free	2,4	1,6	0,8	free
8462 21 10	— — — For working flat products						
8462 21 80	— — — Other						
8462 29	— — Other						
8462 29 05	— — — Of a kind used in manufacturing semiconductor devices	1,7	free	1,3	0,8	0,4	free
	— — — For working flat products						
	— — — Other						
8462 29 91	— — — Hydraulic						
8462 29 99	— — — Other						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8464	Machine-tools for working stone, ceramics, concrete, asbestos-cement or like mineral materials or for cold working glass:						
8464 10	— Sawing machines						
8464 10 10	— — For sawing monocrystal semiconductor boules into slices, or wafers into chips	free	free	free	free	free	free
8464 10 90	— — Other						
9464 20	— Grinding or polishing machines						
8464 20 05	— — For working semiconductor wafers	free	free	free	free	free	free
	— — For working glass						
8464 20 11	— — — Optical glass						
8464 20 19	— — — Other						
8464 20 80	— — Other						
8464 90	— Other						
8464 90 10	— — For scribing or scoring semiconductor wafers	free	free	free	free	free	free
8464 90 90	— — Other						
8466	Parts and accessories suitable for use solely or principally with the machines of heading Nos 8456 to 8465, including work or tool holders, self-opening dieheads, dividing heads and other special attachments for machine-tools; tool holders for any type of tool for working in the hand:						
	— Other						
8466 91	— — For machines of heading No 8464						
8466 91 15	— — — For machines of subheading 8464 10 10, 8464 20 05 or 8464 90 10	1,9	free	1,4	0,9	0,5	free
8466 91 20	— — — Of cast iron or cast steel						
8466 91 95	— — — Other						
8466 93	— — For machines of heading Nos 8456 to 8461						
8466 93 15	— — — For machines and apparatus of subheading 8456 10 10, 8456 91 00, 8456 99 10 or 8456 99 30	1,9	free	1,4	0,9	0,5	free
8466 93 20	— — — Of cast iron or cast steel						
8466 93 95	— — — Other						
8466 94	— — For machines of heading No 8462 or 8463						
8466 94 10	— — — For machines of subheading 8462 21 05 or 8452 29 05	1,9	free	1,4	0,9	0,5	free
8466 94 90	— — — Other						
	— Automatic typewriters and word-processing machines						
8469 11 00	— — Word-processing machines	3,2	free	2,4	1,6	0,8	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8470	Calculating machines and pocket-size data recording, reproducing and displaying machines with calculating functions; accounting machines, postage-franking machines, ticket-issuing machines and similar machines, incorporating a calculating device; cash registers:						
8470 10	– Electronic calculators capable of operation without an external source of electric power and pocket-size data recording, reproducing and displaying machines with calculating functions						
8470 10 10	– – Electronic calculators capable of operation without an external source of electric power	8,4	free	6,3	4,2	2,1	free
8470 10 90	– – Pocket-size data recording, reproducing and displaying machines with calculating functions	5,0	free	3,8	2,5	1,3	free
	– Other electronic calculating machines						
8470 21 00	– – Incorporating a printing device	8,4	free	6,3	4,2	2,1	free
8470 29 00	– – Other	8,4	free	6,3	4,2	2,1	free
8470 30 00	– Other calculating machines	2,8	free	2,1	1,4	0,7	free
8470 40 00	– Accounting machines	2,8	free	2,1	1,4	0,7	free
8470 50 00	– Cash registers	2,8	free	2,1	1,4	0,7	free
8470 90 00	– Other	2,8	free	2,1	1,4	0,7	free
8471	Automatic data-processing machines and units thereof; magnetic or optical readers, machines for transcribing data onto data media in coded form and machines for processing such data, not elsewhere specified or included:						
8471 10	– Analogue or hybrid automatic data-processing machines						
8471 10 10	– – For use in civil aircraft	free	free	free	free	free	free
8471 10 90	– – Other	3,5	free	2,6	1,8	0,9	free
8471 30 00	– Portable digital automatic data-processing machines, weighing not more than 10 kg, consisting of at least a central processing unit, a keyboard and a display	3,5	free	2,6	1,8	0,9	free
	– Other digital automatic data-processing machines						
8471 41	– – Comprising in the same housing at least a central processing unit and an input and output unit, whether or not combined						
8471 41 10	– – – For use in civil aircraft	free	free	free	free	free	free
8471 41 90	– – – Other	3,5	free	2,6	1,8	0,9	free
8471 49	– – Other, presented in the form of systems						
8471 49 10	– – – For use in civil aircraft	free	free	free	free	free	free
8471 49 90	– – – Other	3,5	free	2,6	1,8	0,9	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8471 50	— Digital processing units other than those of subheadings No 8471 41 and 8471 49, whether or not containing in the same housing one or two of the following types of unit: storage units, input units, output units						
8471 50 10	— — For use in civil aircraft	free	free	free	free	free	free
8471 50 90	— — Other	3,5	free	2,6	1,8	0,9	free
8471 60	— Input or output units, whether or not containing storage units in the same housing						
8471 60 10	— — For use in civil aircraft	free	free	free	free	free	free
	— — Other						
8471 60 40	— — — Printers	2	free	1,5	1,0	free	free
8471 60 50	— — — Keyboards	2	free	1,5	1,0	free	free
8471 60 90	— — — Other	2	free	1,5	1,0	free	free
8471 70	— Storage units						
8471 70 10	— — For use in civil aircraft	free	free	free	free	free	free
	— — Other						
8471 70 40	— — — Central storage units	2	free	1,5	1,0	free	free
	— — — Other						
	— — — — Disk storage units						
8471 70 51	— — — — — Optical, including magneto-optical	2	free	1,5	1,0	free	free
	— — — — — Other						
8471 70 53	— — — — — — Hard disk drives	1,6	free	1,2	0,8	free	free
8471 70 59	— — — — — — Other	2	free	1,5	1,0	free	free
8471 70 60	— — — — Magnetic tape storage units	2	free	1,5	1,0	free	free
8471 70 90	— — — — Other	2	free	1,5	1,0	free	free
8471 80	— Other units of automatic data-processing machines						
8471 80 10	— — Peripheral units	2	free	1,5	1,0	free	free
8471 80 90	— — Other	2	free	1,5	1,0	free	free
8471 90 00	— Other						
8472	Other office machines (for example, hectograph or stencil duplicating machines, addressing machines, automatic banknote dispensers, coin-sorting machines, coin-counting or wrapping machines, pencil-sharpening machines, perforating or stapling machines):						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8472 90	– Other						
8472 90 10	– – Coin-sorting, coin-counting or coin-wrapping machines						
8472 90 30	– – Automatic teller machines	3,1	free	2,3	1,6	0,8	free
8472 90 80	– – Other						
8473	Parts and accessories (other than covers, carrying cases and the like) suitable for use solely or principally with machines of heading Nos 8469 to 8472:						
8473 10	– Parts and accessories of the machines of heading No 8469						
8473 10 11	– – Printed circuit assemblies for products of subheading No 8469 11	3,4	free	2,5	1,7	0,8	free
8473 10 19	– – Other						
8473 21	– – Of the electronic calculating machines of subheading 8470 10, 8470 21 or 8470 29						
8473 21 10	– – – Electronic assemblies	4,3	free	3,2	2,1	1,1	free
8473 21 90	– – – Other	2,5	free	1,9	1,3	free	free
8473 29	– – Other						
8473 29 10	– – – Electronic assemblies	3,4	free	2,5	1,7	0,8	free
8473 29 90	– – – Other	1,6	free	1,2	0,8	free	free
8473 30	– Parts and accessories of the machines of heading No 8471						
8473 30 10	– – Electronic assemblies	3,3	free	2,5	1,6	0,8	free
8473 30 90	– – Other	1,6	free	1,2	0,8	free	free
8473 40	– Parts and accessories of the machines of heading No 8472						
8473 40 11	– – Printed circuit assemblies for products of subheading No 8472 90 30	3,4	free	2,5	1,7	0,8	free
8473 40 19	– – Other						
8473 50	– Parts and accessories equally suitable for use with machines of two or more of the headings Nos 8469 to 8472						
8473 50 10	– – Electronic assemblies	3,4	free	2,5	1,7	0,8	free
8473 50 90	– – Other	1,6	free	1,2	0,8	free	free
8477	Machinery for working rubber or plastics or for the manufacture of products from these materials, not specified or included elsewhere in this chapter:						
8477 10	– Injection-moulding machines						
8477 10 10	– – Encapsulation equipment for assembly of semiconductors	2,8	free	2,1	1,4	0,7	free
8477 10 90	– – Other						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8477 59	— — Other						
8477 59 05	— — — Encapsulation equipment for assembly of semiconductors	2,8	free	2,1	1,4	0,7	free
8477 59 10	— — — Presses						
8477 59 90	— — — Other						
8477 90	— Parts						
8477 90 05	— — For machines of subheadings 8477 10 10 and 8477 59 05	2,8	free	2,1	1,4	0,7	free
8477 90 10	— — Of cast iron or cast steel						
8477 90 80	— — Other						
8479	Machines and mechanical appliances having individual functions, not specified or included elsewhere in this chapter:						
8479 89	— — Other						
8479 89 10	— — — The following goods, for use in civil aircraft: hydropneumatic batteries; mechanical actuators for thrust reversers; toilet units specially designed; air humidifiers and dehumidifiers; servo-mechanisms, non-electric; non-electric starter motors; pneumatic starters for turbo-jets, turbo-jets, turbo-propellers and other gas turbines; windscreen wipers, non-electric; propeller regulators, non-electric						
	— — — Other						
8479 89 30	— — — — Mobile hydraulic powered mine roof supports						
8479 89 60	— — — — Central greasing systems						
8479 89 65	— — — — Apparatus for growing or pulling monocrystal semiconductor boules	free	free	free	free	free	free
8479 89 70	— — — — Apparatus for epitaxial deposition on semiconductor wafers	free	free	free	free	free	free
8479 89 75	— — — — Apparatus for wet etching, developing, stripping or cleaning semiconductor wafers	free	free	free	free	free	free
8479 89 76	— — — — Apparatus for wet etching, developing, stripping or cleaning liquid crystal display substrates	2,8	free	2,1	1,4	0,7	free
8479 89 77	— — — — Die attach apparatus and tape automated bonders for the assembly of semiconductors	2,8	free	2,1	1,4	0,7	free
8479 89 79	— — — — Encapsulation equipment for assembly of semiconductors	2,8	free	2,1	1,4	0,7	free
8479 89 95	— — — — Other						
8479 90	— Parts						
8479 90 10	— — For use in civil aircraft						
	— — Other						
8479 90 50	— — — Of machines of subheadings 8479 89 65, 8479 89 70, 8479 89 75, 8479 89 76, 8479 89 77 or 8479 89 79	2,8	free	2,1	1,4	0,7	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8477 90	— Parts						
8477 90 05	— — For machines of subheadings 8477 10 10 and 8477 59 05	2,8	free	2,1	1,4	0,7	free
8477 90 10	— — Of cast iron or cast steel						
8477 90 80	— — Other						
8479	Machines and mechanical appliances having individual functions, not specified or included elsewhere in this chapter:						
8479 89	— — Other						
8479 89 10	— — — The following goods, for use in civil aircraft: hydropneumatic batteries; mechanical actuators for thrust reversers; toilet units specially designed; air humidifiers and dehumidifiers; servo-mechanisms, non-electric; non-electric starter motors; pneumatic starters for turbo-jets, turbo-jets, turbo-propellers and other gas turbines; windscreen wipers, non-electric; propeller regulators, non-electric						
	— — — Other						
8479 89 30	— — — — Mobile hydraulic powered mine roof supports						
8479 89 60	— — — — Central greasing systems						
8479 89 65	— — — — Apparatus for growing or pulling monocrystal semiconductor boules	free	free	free	free	free	free
8479 89 70	— — — — Apparatus for epitaxial deposition on semiconductor wafers	free	free	free	free	free	free
8479 89 75	— — — — Apparatus for wet etching, developing, stripping or cleaning semiconductor wafers	free	free	free	free	free	free
8479 89 76	— — — — Apparatus for wet etching, developing, stripping or cleaning liquid crystal display substrates	2,8	free	2,1	1,4	0,7	free
8479 89 77	— — — — Die attach apparatus and tape automated bonders for the assembly of semiconductors	2,8	free	2,1	1,4	0,7	free
8479 89 79	— — — — Encapsulation equipment for assembly of semiconductors	2,8	free	2,1	1,4	0,7	free
8479 89 95	— — — — Other						
8479 90	— Parts						
8479 90 10	— — For use in civil aircraft						
	— — Other						
8479 90 50	— — — Of machines of subheadings 8479 89 65, 8479 89 70, 8479 89 75, 8479 89 76, 8479 89 77 or 8479 89 79	2,8	free	2,1	1,4	0,7	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8479 90 92	— — — Of cast iron or cast steel						
8479 90 98	— — — Other						
8480	Moulding boxes for metal foundry; mould bases; moulding patterns; moulds for metal (other than ingot moulds), metal carbides, glass, mineral materials, rubber or plastics:						
	— Moulds for rubber or plastics						
8480 71	— — Injection or compression types						
8480 71 10	— — — of a kind used in the manufacturing of semiconductor devices	2,5	free	1,9	1,3	0,6	free
8480 71 90	— — — Other						
8504	Electrical transformers, static converters (for example, rectifiers) and inductors:						
8504 40	— Static converters						
8504 40 10	— — For use in civil aircraft						
	— — Other						
	— — — Of a kind used with telecommunication apparatus and automatic data-processing machines and units thereof:						
8504 40 30	— — — — Power supply units of a kind used with automatic data-processing machines	2	free	1,5	1,0	free	free
8504 40 35	— — — — Other	4,6	free	3,4	2,3	1,1	free
	— — — Other						
8504 40 50	— — — — Polycrystalline semiconductors						
	— — — — Other						
8504 40 93	— — — — — Accumulator chargers						
	— — — — — Other						
8504 40 94	— — — — — — Rectifiers						
	— — — — — — Inverters						
8504 40 96	— — — — — — — Having a power handling capacity not exceeding 7,5 kVA						
8504 40 97	— — — — — — — Having a power handling capacity exceeding 7,5 kVA						
8504 40 99	— — — — — — Other						
8504 50	— Other inductors						
8504 50 10	— — For use in civil aircraft						
	— — Other						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8504 50 30	— — — Of a kind used for telecommunication apparatus and power supplies for automatic data processing machines and units thereof	4,8	free	3,6	2,4	1,2	free
8504 50 80	— — — Other						
8504 90	— Parts						
	— — Of transformers and inductors						
8504 90 05	— — — — Printed circuit assemblies for products of subheading 8504 50 30	3,1	free	2,3	1,6	0,8	free
	— — — Other						
8504 90 11	— — — — Ferrite cores						
8505 90 18	— — — Other						
	— — — — Of static converters						
8504 90 91	— — — — Printed circuits assemblies for products of subheadings 8504 40 30 and 8504 40 35	3,1	free	2,3	1,6	0,8	free
8504 90 99	— — — — Other						
8514	Industrial or laboratory electric (including induction or dielectric) furnaces and ovens; other industrial or laboratory induction or dielectric heating equipment:						
8514 10	— Resistance heated furnaces and ovens						
8514 10 05	— — For the manufacture of semiconductor devices on semiconductor wafers	3	free	2,3	1,5	0,8	free
	— — Other						
8514 10 10	— — — Bakery and biscuit ovens						
8514 10 90	— — — Other						
8514 20	— Induction or dielectric furnaces and ovens						
8514 20 05	— — For the manufacture of semiconductor devices on semiconductor wafers	3	free	2,3	1,5	0,8	free
	— — — Other						
8514 20 10	— — Induction furnaces and ovens						
8514 20 90	— — Dielectric furnaces and ovens						
8514 30	— Other furnaces and ovens						
	— — Infra-red radiation ovens						
8514 30 11	— — — For the manufacture of semiconductor devices on semiconductor wafers	free	free	free	free	free	free
8514 39 19	— — — Other						
	— — Other						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8514 30 91	— — — For the manufacture of semiconductor devices on semiconductor wafers	free	free	free	free	free	free
8514 30 99	— — — Other						
8514 90	— Parts						
8514 90 10	— — Of apparatus of subheading 8514 10 05, 8514 20 05, 8514 30 11 or 8514 30 91	3	free	2,3	1,5	0,8	free
8514 90 90	— — Other						
8515	Electric (including electrically heated gas), laser or other light or photon beam, ultrasonic, electron beam, magnetic pulse or plasma arc soldering, brazing or welding machines and apparatus, whether or not capable of cutting; electric machines and apparatus for hot spraying of metals or cermets						
	— Brazing or soldering machines and apparatus						
8515 11 00	— — Soldering irons and guns						
8515 19 00	— — Other						
	— Machines and apparatus for resistance welding of metal						
8515 21 00	— — Fully or partly automatic						
8515 29	— — Other						
8515 29 10	— — — For butt welding						
8515 29 90	— — — Other						
	— Machines and apparatus for arc (including plasma arc) welding of metals						
8515 31 00	— — Fully or partly automatic						
8515 39	— — Other						
	— — — For manual welding with coated electrodes, complete with welding or cutting devices, and consigned with						
8515 39 13	— — — — Transformers						
8515 39 18	— — — — Generators or rotary converters or static converters, rectifiers or rectifying apparatus						
8515 39 90	— — — Other						
8515 80	— Other machines and apparatus						
8515 80 05	— — Wire bonders of a kind used for manufacturing semiconductor devices	3,7	free	2,8	1,9	0,9	free
	— — Other						
	— — — For treating metals						
8515 80 11	— — — — For welding						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8515 80 19	– – – – Other						
	– – – Other						
8515 80 91	– – – – For resistance welding of plastics						
8515 80 99	– – – – Other						
8515 90	– Parts						
8515 90 10	– – For machines of subheading 8515 80 05	3,7	free	2,8	1,9	0,9	free
8515 90 90	– – Other						
8517	Electrical apparatus for line telephony or line telegraphy, including line telephone sets with cordless handsets and telecommunication apparatus for carrier-current line systems or for digital line systems; videophones:						
	– Telephone sets; videophones						
8517 11 00	– – Line telephone sets with cordless handsets	7,5	free	5,6	3,8	1,9	free
8517 19	– – Other						
9517 19 10	– – – Videophones	14	free	10,5	7,0	3,5	free
8517 19 90	– – – Other	7,5	free	5,6	3,8	1,9	free
	– Facsimile machines and teleprinters						
8517 21 00	– – Facsimile machines	7,5	free	5,6	3,8	1,9	free
8517 22 00	– – Teleprinters	7,5	free	5,6	3,8	1,9	free
8517 30 00	– Telephonic or telegraphic switching apparatus	7,5	free	5,6	3,8	1,9	free
8517 50	– Other apparatus, for carrier-current line systems or for digital line systems						
8517 50 10	– – For carrier-current line systems	4,6	free	3,4	2,3	1,1	free
8517 50 90	– – Other	7,5	free	5,6	3,8	1,9	free
8517 80	– Other apparatus						
8517 80 10	– – Entry-phone systems	7,5	free	5,6	3,8	1,9	free
8517 80 90	– – Other	7,5	free	5,6	3,8	1,9	free
8517 90	– Parts						
	– – Of apparatus for carrier-current line systems of subheading 8517 50 10						
8517 90 11	– – – Electronic assemblies	4,6	free	3,4	2,3	1,1	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8517 90 19	— — — Other	4,6	free	3,4	2,3	1,1	free
	— — Other						
8517 90 82	— — — Electronic assemblies	7,5	free	5,6	3,8	1,9	free
8517 90 88	— — — Other	7,5	free	5,6	3,8	1,9	free
8518	Microphones and stands therefor; loudspeakers, whether or not mounted in their enclosures; headphones, earphones and combined microphone/speaker sets; audio-frequency electric amplifiers; electric sound amplifier sets:						
8518 10	— Microphones and stands therefor						
8518 10 10	— — Other						
8518 10 20	Microphones having a frequency range of 300 Hz to 3,4 KHz with a diameter not exceeding 10 mm and a height not exceeding 3 mm, for telecommunications use	3,5	free	2,6	1,8	0,9	free
8518 10 80	— — — Other						
8518 29	— — Other						
8518 29 10	— — — For use in civil aircraft						
8518 29 20	— — — Loudspeakers having a frequency range of 300 Hz to 3,4 KHz with a diameter not exceeding 50 mm, for telecommunications use	3,8	free	2,8	1,9	0,9	free
8518 29 80	— — — Other						
8518 30	— Headphones, earphones and combined microphone/speaker sets						
8518 30 10	— — For use in civil aircraft						
8518 30 20	— — Line telephone handsets	4	free	3,0	2,0	1,0	free
8518 30 80	— — Other						
8520	Magnetic tape recorders and other sound recording apparatus, whether or not incorporating a sound reproducing device:						
8520 20 00	— Telephone answering machines	5,2	free	3,9	2,6	1,3	free
8522	Parts and accessories suitable for use solely or principally with the apparatus of headings Nos 8519 to 8521						
8522 10 00	— Pick-up cartridges						
8522 90	— Other						
8522 90 10	— — Assemblies and sub-assemblies consisting of two or more parts or pieces fastened or joined together, for apparatus falling within subheading 8520 90, for use in civil aircraft						
	— — Other						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8522 90 30	— — — Styli; diamonds, sapphires and other precious or semi-precious stones (natural, synthetic or reconstructed) for styli, whether or not mounted						
	— — — Other						
	— — — — Electronic assemblies						
8522 90 51	— — — — — Printed circuit assemblies for products of subheading 8520 20 00	4,7	free	3,5	2,4	1,2	free
8522 90 59	— — — — — Other						
8522 90 93	— — — — Single cassette-deck assemblies with a total thickness not exceeding 53 mm, of a kind used in the manufacture of sound recording and reproducing apparatus						
8522 90 98	— — — — Other						
8523	Prepared unrecorded media for sound recording or similar recording of other phenomena, other than products of Chapter 37:						
	— Magnetic tapes						
8523 11 00	— — Of a width not exceeding 4 mm	3,2	free	2,4	1,6	0,8	free
8523 12 00	— — Of a width exceeding 4 mm but not exceeding 6,5 mm	4,1	free	3,1	2,0	1,0	free
8523 13 00	— — Of a width exceeding 6,5 mm	4,1	free	3,1	2,0	1,0	free
8523 20	— Magnetic discs						
	— — Rigid						
8523 20 11	— — — With a thin film metallic coating, having a coercivity exceeding 600 Oersted and an external diameter not exceeding 231 mm	2	free	1,5	1,0	free	free
8523 20 19	— — — Other	4,1	free	3,1	2,0	1,0	free
8523 20 90	— — Other	4,1	free	3,1	2,0	1,0	free
8523 90 00	— Other	4,1	free	3,1	2,0	1,0	free
8524	Records, tapes and other recorded media for sound or other similarly recorded phenomena, including matrices and masters for the production of records, but excluding products of Chapter 37:						
	— Discs for laser reading systems						
8524 31 00	— — For reproducing phenomena other than sound or image	4,1	free	3,1	2,0	1,0	free
8524 32 00	— — For reproducing sound only						
8524 39	— — Other						
8524 39 10	— — — For reproducing representations of instructions, data, sound and image recorded in a machine readable binary form, and capable of being manipulated or providing interactivity to the user, by means of an automatic data processing machine						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8524 39 90	— — — Other						
8524 40	— Magnetic tapes for reproducing phenomena other than sound or image						
8524 40 10	— — Bearing data or instructions of a kind used in automatic data-processing machines	2	free	1,5	1,0	free	free
	— — Other,						
8524 40 91	— — — Of a width exceeding 4 mm but not exceeding 6,5 mm	3,6	free	2,7	1,8	0,9	free
8524 40 99	— — — Other	4,1	free	3,1	2,0	1,0	free
	— Other						
8524 91	— — For reproducing phenomena other than sound or image						
8524 91 10	— — — Bearing data or instructions of a kind used in automatic data-processing machines	2	free	1,5	1,0	free	free
8524 91 90	— — — Other	4,1	free	3,1	2,0	1,0	free
8524 99	— — Other						
8524 99 10	— — — For reproducing representations of instructions, data, sound and image recorded in a machine readable binary form, and capable of being manipulated or providing interactivity to the user, by means of an automatic data processing machine						
8524 99 90	— — — Other						
8525	Transmission apparatus for radio-telephony, radio-telegraphy, radio-broadcasting or television, whether or not incorporating reception apparatus or sound recording or reproducing apparatus; television cameras; still image video cameras and other video camera recorders:						
8525 10	— Transmission apparatus						
	— — Radio-telegraphic or radio-telephonic apparatus:						
8525 10 10	— — — for use in civil aircraft						
	— — — Other						
8525 10 50	— — — — Radio-telegraphic or radio-telephonic apparatus	4,1	free	3,1	2,0	1,0	free
8525 10 80	— — — — Other						
8525 20	— Transmission apparatus incorporating reception apparatus						
8525 20 10	— — Radio-telegraphic or radio-telephonic apparatus, for use in civil aircraft	free	free	free	free	free	free
	— — Other						
8525 20 91	— — — For cellular networks (mobile telephones)	6,5	free	4,9	3,3	1,6	free
8525 20 99	— — — Other	6,5	free	4,9	3,3	1,6	free
8525 40	— Still image video cameras and other video camera recorders						
	— — Still image video cameras						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8525 40 11	— — — Digital	4,9	free	3,7	2,5	1,2	free
8525 40 19	— — — Other						
	— — Other video camera recorders						
8525 40 91	— — — Only able to record sound and images taken by the television camera						
8525 40 99	— — — Other						
8527	Reception apparatus for radio-telephony, radio-telegraphy or radio-broadcasting, whether or not combined, in the same housing, with sound recording or reproducing apparatus or a clock:						
8527 90	— Other apparatus						
8527 90 10	For radio-telephony or radio-telegraphy, for use in civil aircraft						
	— — Other						
8527 90 92	— — — Portable receivers for calling, alerting or paging	9,6	free	7,2	4,8	2,4	free
8527 90 98	— — — Other						
8528	Reception apparatus for television, whether or not incorporating radio-broadcast receivers or sound or video recording or reproducing apparatus; video monitors and video projectors:						
	— Reception apparatus for television, whether or not incorporating radio-broadcast receivers or sound or video recording or reproducing apparatus						
8528 12	— — Colour						
8528 12 10	— — — Apparatus combined with an automatic data processing machine, freely programmable by the user	14	free	10,5	7,0	3,5	free
	— — — Other						
	— — — — Television projection equipment						
8528 12 14	— — — — — With scanning parameters not exceeding 625 lines						
	— — — — — With scanning parameters exceeding 625 lines						
8528 12 16	— — — — — — With a vertical resolution of less than 700 lines						
8528 12 18	— — — — — — With a vertical resolution of 700 lines or more						
	— — — — Apparatus incorporating a video recorder or reproducer						
8528 12 22	— — — — — With a screen width/height ratio less than 1,5						
8528 12 28	— — — — — Other						
	— — — — Other						
	— — — — — With integral tube						
	— — — — — — With a screen width/height ratio less than 1,5, with a diagonal measurement of the screen						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8528 12 52	— — — — — — — Not exceeding 42 cm						
8528 12 54	— — — — — — — Exceeding 42 cm but not exceeding 52 cm						
8528 12 56	— — — — — — — Exceeding 52 cm but not exceeding 72 cm						
8528 12 58	— — — — — — — Exceeding 72 cm						
	— — — — — — Other						
	— — — — — — — With scanning parameters not exceeding 625 lines, with a diagonal measurement of the screen						
8528 12 62	— — — — — — — — Not exceeding 75 cm						
8528 12 66	— — — — — — — — Exceeding 75 cm						
	— — — — — — — With scanning parameters not exceeding 625 lines						
8528 12 72	— — — — — — — — With a vertical resolution of less than 700 lines						
8528 12 76	— — — — — — — — With a vertical resolution of 700 lines or more						
	— — — — — Other						
	— — — — — — With screen						
8528 12 81	— — — — — — — With a screen width/height ratio less than 1,5						
8628 12 89	— — — — — — — Other						
	— — — — — — Without screen						
	— — — — — — — Video tuners						
8528 12 90	— — — — — — — — Printed circuit assemblies for physical incorporation into an automatic data processing machine	14,0	free	10,5	7,0	3,5	free
	— — — — — — — Other						
8528 12 92	— — — — — — — — Digital (including mixed digital and analogue)						
8528 12 94	— — — — — — — — Other						
8528 12 98	— — — — — — Other						
8528 13	— — Black and white or other monochrome						
8528 13 10	— — — Apparatus combined with an automatic data processing machine, freely programmable by the user	6,8	free	5,1	3,4	1,7	free
8528 13 90	— — — Other						
8528 30	— Video projectors						
8528 30 05	— — Of the flat panel type, capable of displaying digital information generated by the central processing unit of an automatic data processing machine	14	free	10,5	7,0	3,5	free
	— — Other						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8528 30 20	— — — Colour						
8528 30 90	— — — Black and white or other monochrome						
8529	Parts suitable for use solely or principally with the apparatus of heading Nos 8525 to 8528:						
8529 10	— Aerials and aerial reflectors of all kinds; parts suitable for use therewith						
8529 10 10	— — For use in civil aircraft						
	— — Other						
	— — — Aerials						
8529 10 15	— — — — Aerials of a kind used with apparatus for radio-telephony and radio-telegraphy	5	free	3,8	2,5	1,3	free
8529 10 20	— — — — Telescopic and whip-type aerials for portable apparatus or for apparatus for fitting in motor vehicles						
	— — — — Outside aerials for radio or television broadcast receivers						
8529 10 31	— — — — — For reception via satellite						
8529 10 39	— — — — — Other						
8529 10 40	— — — — Inside aerials for radio or television broadcast receivers, including built-in types						
8529 10 50	— — — — Other						
8529 10 70	— — — Aerial filters and separators						
8529 10 80	— — — Other						
8529 90	— Other						
8529 90 10	— — Assemblies and sub-assemblies consisting of two or more parts or pieces fastened or joined together, for apparatus falling within subheadings 8526 10 10, 8526 91 11, 8526 91 19 and 8526 92 10, for use in civil aircraft						
	— — Other						
8529 90 40	— — — Parts of apparatus falling within subheadings 8525 10 50, 8525 20 99, 8525 40 11 or 8527 90 92	4,7	free	3,5	2,4	1,2	free
	— — — Cabinets and cases						
8529 90 51	— — — — Of wood						
8529 90 59	— — — — Of other materials						
8529 90 70	— — — Electronic assemblies						
	— — — Other						
8529 90 81	— — — — For television cameras of subheading No 8525 30 and apparatus of heading Nos 8527 and 8528						
8529 90 89	— — — — Other						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8531	Electric sound or visual signalling apparatus (for example, bells, sirens, indicator panels, burglar or fire alarms), other than those of heading No 8512 or 8530:						
8531 20	– Indicator panels incorporating liquid crystal devices (LCD) or light emitting diodes (LED)						
8531 20 10	– – For use in civil aircraft	free	free	free	free	free	free
	– – Other						
8531 20 30	– – – Incorporating light emitting diodes (LED)	4,2	free	3,2	2,1	1,1	free
	– – – Incorporating liquid crystal devices (LCD)						
	– – – Incorporating active matrix liquid crystal devices (LCD)						
8531 20 51	– – – – – Colour	4,2	free	3,2	2,1	1,1	free
8531 20 59	– – – – – Black and white or other monochrome	4,2	free	3,2	2,1	1,1	free
8531 20 80	– – – Other	4,2	free	3,2	2,1	1,1	free
8531 80	– Other apparatus						
8531 80 10	– – For use in civil aircraft						
	– – Other						
8531 80 30	– – – Flat panel display devices	3,1	free	2,3	1,6	0,8	free
8531 80 80	– – – Other						
8531 90	– Parts						
8531 90 10	– – Of apparatus of subheading No 8531 20	4,2	free	3,2	2,1	1,1	free
8531 90 30	– – Of apparatus of subheading 8531 80 30	3,1	free	2,3	1,6	0,8	free
8531 90 80	– – Other						
8532	Electrical capacitors, fixed, variable or adjustable (pre-set):						
8532 10 00	– Fixed capacitors designed for use in 50/60 Hz circuits and having a reactive power handling capacity of not less than 0,5 kvar (power capacitors)	3,6	free	2,7	1,8	0,9	free
	– Other fixed capacitors						
8532 21 00	– – Tantalum	5	free	3,8	2,5	1,3	free
8532 22 00	– – Aluminium electrolytic	5	free	3,8	2,5	1,3	free
8532 23 00	– – Ceramic dielectric, single layer	3,6	free	2,7	1,8	0,9	free
	– – Ceramic dielectric, multilayer						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8532 24 10	— — — With connecting leads	3,6	free	2,7	1,8	0,9	free
8532 24 90	— — — Other	3,6	free	2,7	1,8	0,9	free
8532 25 00	— — Dielectric of paper or plastics	3,6	free	2,7	1,8	0,9	free
8532 29 00	— — Other	3,6	free	2,7	1,8	0,9	free
8532 30 00	— Variable or adjustable (pre-set) capacitors	5	free	3,8	2,5	1,3	free
8532 90 00	— Parts	4,7	free	3,5	2,4	1,2	free
8533	Electrical resistors (including rheostats and potentiometers), other than heating resistors:						
8533 10 00	— Fixed carbon resistors, composition or film types	3,7	free	2,8	1,9	0,9	free
	— Other fixed resistors						
8533 21 00	— — For a power handling capacity not exceeding 20 W	3,7	free	2,8	1,9	0,9	free
8533 29 00	— — Other	3,7	free	2,8	1,9	0,9	free
	— Wirewound variable resistors, including rheostats and potentiometers						
8533 31 00	— — For a power handling capacity not exceeding 20 W	3,7	free	2,8	1,9	0,9	free
8533 39 00	— — Other	3,7	free	2,8	1,9	0,9	free
8533 40	— Other variable resistors, including rheostats and potentiometers						
8533 40 10	— — For a power handling capacity not exceeding 20 W	3,7	free	2,8	1,9	0,9	free
8533 40 90	— — Other	3,7	free	2,8	1,9	0,9	free
8533 90 00	— Parts	3,7	free	2,8	1,9	0,9	free
8534	Printed circuits						
	— Consisting only of conductor elements and contacts						
8534 00 11	— — Multiple circuits	5,2	free	3,9	2,6	1,3	free
8534 00 19	— — Other	5,2	free	3,9	2,6	1,3	free
8534 00 90	— With other passive elements	5,2	free	3,9	2,6	1,3	free
8536	Electrical apparatus for switching or protecting electrical circuits, or for making connections to or in electrical circuits (for example, switches, relays, fuses, surge suppressors, plugs, sockets, lamp-holders, junction boxes), for a voltage not exceeding 1 000 V:						
8536 50	— Other switches						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8536 50 03	— — Electronic AC switches consisting of optically coupled input and output circuits (insulated thyristor AC switches)	3,2	free	2,4	1,6	0,8	free
8536 50 05	— — Electronic switches, including temperature protected electronic switches, consisting of a transistor and a logic chip (chip-on-chip technology)	3,2	free	2,4	1,6	0,8	free
8536 50 07	— — Electromechanical snap-acion switches for a current not exceeding 11 amps	3,2	free	2,4	1,6	0,8	free
	— — Other						
	— — — For a voltage not exceeding 60 V						
8536 50 11	— — — — Push-button switches						
8536 50 15	— — — — Rotary switches						
8536 50 19	— — — — Other						
8536 50 90	— — — Other						
8536 69	— — Other						
8536 69 10	— — — For co-axial cables	3,2	free	0,0	0,0	0,0	free
8536 69 30	— — — For printed circuits	3,2	free	0,0	0,0	0,0	free
8536 69 90	— — — Other						
8536 90	— Other apparatus						
8536 90 01	— — Prefabricated elements for electrical circuits						
8536 90 10	— — Connections and contact elements for wire and cables	3,2	free	2,4	1,6	0,8	free
8536 90 20	— — Wafer probers	free	free	free	free	free	free
8536 90 85	— — Other						
8541	Diodes, transistors and similar semiconductor devices; photosensitive semiconductor devices, including photovoltaic cells whether or not assembled in modules or made up into panels; light-emitting diodes; mounted piezo-electric crystals:						
8541 10	— Diodes, other than photosensitive or light-emitting diodes						
8541 10 10	— — Wafers not yet cut into chips	7	free	3,5	1,8	free	free
	Other						
8541 10 91	— — — Power rectifier diodes	7	free	3,5	1,8	free	free
8541 10 99	— — — Other	7	free	3,5	1,8	free	free
	— Transistors, other than photosensitive transistors						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8541 21	— — With a dissipation rate of less than 1 W						
8541 21 10	— — — Wafers not yet cut into chips	7	free	3,5	1,8	free	free
8541 21 90	— — — Other	7	free	3,5	1,8	free	free
8541 29	— — Other						
8541 29 10	— — — Wafers not yet cut into chips	7	free	3,5	1,8	free	free
8541 29 20	— — — PowerMOS field effective transistors	7	free	3,5	1,8	free	free
8541 29 30	— — — Insulated gate bipolar transistors (IGBTs)	7	free	3,5	1,8	free	free
8541 29 80	— — — Other	7	free	3,5	1,8	free	free
8541 30	— Thyristors, diacs and triacs, other than photosensitive devices						
8541 30 10	— — Wafers not yet cut into chips	7	free	3,5	1,8	free	free
8541 30 90	— — Other	7	free	3,5	1,8	free	free
8541 40	— Photosensitive semiconductor devices, including photovoltaic cells whether or not assembled in modules or made up into panels; light-emitting diodes						
	— — Light-emitting diodes						
8541 40 11	— — — Laser diodes	7	free	3,5	1,8	free	free
8541 40 19	— — — Other	7	free	3,5	1,8	free	free
	— — Other						
8541 40 91	— — — Solar cells whether or not assembled in modules or made up into panels	3,2	free	1,6	0,8	free	free
8541 40 93	— — — Photodiodes, phototransistors, photothyristors or photocouples	1,8	free	0,9	0,5	free	free
8541 40 99	— — — Other	1,8	free	0,9	0,5	free	free
8541 50	— Other semiconductor devices						
8541 50 10	— — Wafers not yet cut into chips	7	free	3,5	1,8	free	free
8541 50 90	— — Other	7	free	3,5	1,8	free	free
8541 60 00	— Mounted piezo-electric crystals	5,6	free	2,8	1,4	free	free
8541 90 00	— Parts	4,1	free	2,0	1,0	free	free
8542	Electronic integrated circuits and microassemblies:						
	— Monolithic digital integrated circuits						
8542 12 00	— — Cards incorporating an electronic integrated circuit ('smart' cards)	14	free	7,0	3,5	free	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8542 13	— — Metal oxide semiconductors (MOS technology)						
8542 13 01	— — — Wafers not yet cut into chips	7	free	3,5	1,8	free	free
8542 13 05	— — — Chips	7	free	3,5	1,8	free	free
	— — — Other						
	— — — — Memories						
	— — — — — Dynamic random-access memories (D-RAMs)						
8542 13 11	— — — — — — With a storage capacity not exceeding 4 Mbits	7	free	3,5	1,8	free	free
8542 13 13	— — — — — — With a storage capacity exceeding 4 Mbits but not exceeding 16 Mbits	7	free	3,5	1,8	free	free
8542 13 15	— — — — — — With a storage capacity exceeding 16 Mbits but not exceeding 64 Mbits	7	free	3,5	1,8	free	free
8542 13 17	— — — — — — With a storage capacity exceeding 64 Mbits	7	free	3,5	1,8	free	free
	— — — — — Static random-access memories (S-RAMs), including cache random-access memories (cache-RAMs)						
8542 13 22	— — — — — — With a storage capacity not exceeding 256 Kbits	free	free	free	free	free	free
8542 13 25	— — — — — — With a storage capacity exceeding 256 Kbits but not exceeding 1 Mbit	free	free	free	free	free	free
8542 13 27	— — — — — — With a storage capacity exceeding 1 Mbit	free	free	free	free	free	free
	— — — — — UV erasable, programmable, read only memories (EPROMs)						
8542 13 32	— — — — — — With a storage capacity not exceeding 1 Mbit	free	free	free	free	free	free
8542 13 35	— — — — — — With a storage capacity exceeding 1 Mbit but not exceeding 4 Mbits	free	free	free	free	free	free
8542 13 37	— — — — — — With a storage capacity exceeding 4 Mbits	free	free	free	free	free	free
	— — — — — Electrically erasable, programmable, read only memories (E^2PROMs), including FLASH E^2PROMs						
	— — — — — — FLASH E^2PROMs						
8542 13 41	— — — — — — — With a storage capacity not exceeding 1 Mbit	free	free	free	free	free	free
8542 13 43	— — — — — — — With a storage capacity exceeding 1 Mbit but not exceeding 4 Mbits	free	free	free	free	free	free
8542 13 45	— — — — — — — With a storage capacity exceeding 4 Mbits but not exceeding 16 Mbits	free	free	free	free	free	free
8542 13 47	— — — — — — — With a storage capacity exceeding 16 Mbits	free	free	free	free	free	free
8542 13 49	— — — — — — Other	free	free	free	free	free	free
8542 13 51	— — — — — Read only memories, non-programmable (ROMs); content addressable memories (CAMs); first-in/first-out read/write memories (FIFOs); last-in/first-out read/write memories (LIFOs); ferroelectric memories	free	free	free	free	free	free
8542 13 53	— — — — — Other memories	7	free	3,5	1,8	free	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8542 13 55	— — — — Microprocessors	free	free	free	free	free	free
	— — — — Microcontrollers and microcomputers						
8542 13 61	— — — — — With a processing capacity not exceeding 4 bits	5,6	free	2,8	1,4	free	free
8542 13 63	— — — — — With a processing capacity exceeding 4 bits but not exceeding 8 bits	7	free	3,5	1,8	free	free
8542 13 65	— — — — — With a processing capacity exceeding 8 bits but not exceeding 16 bits	7	free	3,5	1,8	free	free
8542 13 67	— — — — — With a processing capacity exceeding 16 bits but not exceeding 32 bits	7	free	3,5	1,8	free	free
8542 13 69	— — — — — With a processing capacity exceeding 32 bits	7	free	3,5	1,8	free	free
	— — — — Other						
8542 13 70	— — — — — Microperipherals	5,6	free	2,8	1,4	free	free
	— — — — — Other						
8542 13 72	— — — — — — Full custom logic circuits	7	free	3,5	1,8	free	free
8542 13 74	— — — — — — Gate arrays	7	free	3,5	1,8	free	free
8542 13 76	— — — — — — Standard cells	7	free	3,5	1,8	free	free
8542 13 82	— — — — — — Programmable logic circuits	5,6	free	2,8	1,4	free	free
8542 13 84	— — — — — — Standard logic circuits	5,6	free	2,8	1,4	free	free
	— — — — — — Other						
8542 13 91	— — — — — — — Control circuits; interface circuits; interface circuits capable of performing control functions	7	free	3,5	1,8	free	free
8542 13 99	— — — — — — — Other	7	free	3,5	1,8	free	free
8542 14	— — Circuits obtained by bipolar technology						
8542 14 01	— — — Wafers not yet cut into chips	7	free	3,5	1,8	free	free
8542 14 05	— — — Chips	7	free	3,5	1,8	free	free
	— — — Other						
	— — — — Memories						
8542 14 10	— — — — — Dynamic random-access memories (D-RAMs)	7	free	3,5	1,8	free	free
8542 14 15	— — — — — Static random-access memories (S-RAMs), including cache random-access memories (cache-RAMs); read only memories, non-programmable (ROMs); content addressable memories (CAMs); first-in/first-out read/write memories (FIFOs); last-in/first-out read/write memories (LIFOs); ferroelectric memories	free	free	free	free	free	free
8542 14 20	— — — — — Electrically erasable, programmable, read only memories (E^2PROMs), including FLASH E^2PROMs)	free	free	free	free	free	free
8542 14 22	— — — — — UV erasable, programmable, read only memories (EPROMs)	free	free	free	free	free	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8542 14 29	– – – – – Other memories	7	free	3,5	1,8	free	free
8542 14 30	– – – – Microprocessors	free	free	free	free	free	free
	– – – – Microcontrollers and microcomputers						
8542 14 42	– – – – – With a processing capacity not exceeding 4 bits	5,6	free	2,8	1,4	free	free
8542 14 44	– – – – – With a processing capacity exceeding 4 bits	7	free	3,5	1,8	free	free
	– – – – Other						
8542 14 50	– – – – – Microperipherals	5,6	free	2,8	1,4	free	free
	– – – – – Other						
8542 14 60	– – – – – – Full custom logic circuits	7	free	3,5	1,8	free	free
8542 14 65	– – – – – – Gate arrays	7	free	3,5	1,8	free	free
8542 14 70	– – – – – – Standard cells	7	free	3,5	1,8	free	free
8542 14 75	– – – – – – Programmable logic circuits	5,6	free	2,8	1,4	free	free
8542 14 80	– – – – – – Standard logic circuits	5,6	free	2,8	1,4	free	free
	– – – – – – Other						
8542 14 91	– – – – – – – Control circuits; interface circuits; interface circuits capable of performing control functions	7	free	3,5	1,8	free	free
8542 14 99	– – – – – – – Other	7	free	3,5	1,8	free	free
8542 19	– – Other, including circuits obtained by a combination of bipolar and MOS technologies (BIMOS technology)						
8542 19 01	– – – Wafers not yet cut into chips	7	free	3,5	1,8	free	free
8542 19 05	– – – Chips	7	free	3,5	1,8	free	free
	– – – Other						
	– – – – Memories						
8542 19 15	– – – – – Dynamic random-access memories (D-RAMs)	7	free	3,5	1,8	free	free
	– – – – – Static random-access memories (S-RAMs), including cache random-access memories (cache-RAMs)						
8542 19 22	– – – – – – With a storage capacity not exceeding 256 Kbits	free	free	free	free	free	free
8542 19 25	– – – – – – With a storage capacity exceeding 256 Kbits but not exceeding 1 Mbit	free	free	free	free	free	free
8542 19 27	– – – – – – With a storage capacity exceeding 1 Mbit	free	free	free	free	free	free
8542 19 31	– – – – – UV erasable, programmable, read only memories (EPROMs)	free	free	free	free	free	free
8542 19 35	– – – – – Electrically erasable, programmable, read only memories (E^2PROMs), including FLASH E^2PROMs	free	free	free	free	free	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8542 19 41	– – – – – Read only memories, non-programmable (ROMs); content addressable memories (CAMs); first-in/first-out read/write memories (FIFOs); last-in/first-out read/write memories (LIFOs); ferroelectric memories	free	free	free	free	free	free
8542 19 49	– – – – – Other memories	7	free	3,5	1,8	free	free
8542 19 55	– – – – Microprocessors	free	free	free	free	free	free
	– – – – Microcontrollers and microcomputers						
8542 19 62	– – – – – With a processing capacity not exceeding 4 bits	5,6	free	2,8	1,4	free	free
8542 19 68	– – – – – With a processing capacity exceeding 4 bits	7	free	3,5	1,8	free	free
	– – – – Other						
8542 19 71	– – – – – Microperipherals	5,6	free	2,8	1,4	free	free
	– – – – – Other						
8542 19 72	– – – – – – Full custom logic circuits	7	free	3,5	1,8	free	free
8542 19 74	– – – – – – Gate arrays	7	free	3,5	1,8	free	free
8542 19 76	– – – – – – Standard cells	7	free	3,5	1,8	free	free
8542 19 82	– – – – – – Programmable logic circuits	5,6	free	2,8	1,4	free	free
8542 19 84	– – – – – – Standard logic circuits	5,6	free	2,8	1,4	free	free
	– – – – – – Other						
8542 19 92	– – – – – – – Control circuits; interface circuits; interface circuits capable of performing control functions	7	free	3,5	1,8	free	free
8542 19 98	– – – – – – – Other	7	free	3,5	1,8	free	free
8542 30	– Other monolithic integrated circuits						
8542 30 10	– – Wafers not yet cut into chips	7	free	3,5	1,8	free	free
8542 30 20	– – Chips	7	free	3,5	1,8	free	free
	– – Other						
8542 30 30	– – – Amplifiers	7	free	3,5	1,8	free	free
8542 30 50	– – – Voltage and current regulators	7	free	3,5	1,8	free	free
	– – – Control circuits						
8542 30 61	– – – – Smartpower circuits	7	free	3,5	1,8	free	free
	– – – – Other						
8542 30 65	– – – – – Mixed analogue-digital circuits	7	free	3,5	1,8	free	free
8542 30 69	– – – – – Other	7	free	3,5	1,8	free	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8542 30 70	— — — Interface circuits; interface circuits capable of performing control functions	7	free	3,5	1,8	free	free
	— — — Other						
8542 30 91	— — — — Smartpower circuits	7	free	3,5	1,8	free	free
	— — — — Other						
8542 30 95	— — — — — Mixed analogue-digital circuits	7	free	3,5	1,8	free	free
8542 30 99	— — — — — Other	7	free	3,5	1,8	free	free
8542 40	— Hybrid integrated circuits						
8542 40 10	— — Microprocessors, microcontrollers and microcomputers	7	free	3,5	1,8	free	free
8542 40 30	— — Converters	7	free	3,5	1,8	free	free
8542 40 50	— — Amplifiers	7	free	3,5	1,8	free	free
8542 40 90	— — Other	7	free	3,5	1,8	free	free
8542 50 00	— Electronic microassemblies	7	free	3,5	1,8	free	free
8542 90 00	— Parts	4,1	free	2,0	1,0	free	free
8543	Electrical machines and apparatus, having individual functions, not specified or included elsewhere in this Chapter						
	— Particle accelerators						
8543 11 00	— — Ion implanters for doping semiconductor materials	free	free	free	free	free	free
8543 30	— Machines and apparatus for electroplating, electrolysis or electrophoresis						
8543 30 10	— — Apparatus for wet etching, developing, stripping or cleaning semiconductor wafers	free	free	free	free	free	free
8543 30 20	— — Apparatus for wet etching, developing, stripping or cleaning liquid crystal display substrates	5	free	3,8	2,5	1,3	free
8543 30 90	— — Other						
	— Other machines and apparatus						
8543 81 00	— — Proximity cards and tags	5	free	3,8	2,5	1,3	free
8543 89	— — Other						
8543 89 10	— — — Flight recorders, for use in civil aircraft						
8543 89 15	— — — Electrical machines with translation or dictionary functions	5	free	3,8	2,5	1,3	free
8543 89 17	— — — Apparatus combined with an automatic data processing machine, freely programmable by the user	5	free	3,8	2,5	1,3	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8543 89 20	— — — Aerial amplifiers						
	— — — Sunbeds, sunlamps and similar suntanning equipment						
	— — — — For fluorescent tubes using ultraviolet A rays						
8543 89 51	— — — — — With a maximum tube length of 100 cm						
8543 89 55	— — — — — Other						
8543 89 59	— — — — Other						
	— — — Apparatus for physical deposition on semiconductor wafers						
8543 89 70	— — — — by sputtering on semiconductor wafers	free	free	free	free	free	free
8543 89 72	— — — — Other	5	free	3,8	2,5	1,3	free
8543 89 73	— — — Encapsulation equipment for assembly of semiconductors	5	free	3,8	2,5	1,3	free
8543 89 79	— — — Multimedia upgrade kits, for automatic data processing machines and units thereof, put up for retail sale, consisting of, at least, speakers and/or microphones, and a printed circuit assembly that enables the automatic data processing and units thereof to process audio signals (sound cards)	5	free	3,8	2,5	1,3	free
8543 89 90	— — — Other						
8543 90	— Parts						
8543 90 10	— — Assemblies and sub-assemblies consisting of two or more parts or pieces fastened or joined together, for flight recorders, for use in civil aircraft						
8543 90 20	— — Printed circuit assemblies for physical incorporation into an automatic data processing machine	5	free	3,8	2,5	1,3	free
8543 90 30	— — Of apparatus of subheadings 8543 11 00, 8543 30 10, 8543 30 20, 8543 89 70, 8543 89 72 and 8543 89 73	5	free	3,8	2,5	1,3	free
8543 90 90	— — Other						
8544	Insulated (including enamelled or anodised) wire, cable (including coaxial cable) and other insulated electric conductors, whether or not fitted with connectors; optical fibre cables, made up of individually sheathed fibres, whether or not assembled with electric conductors or fitted with connectors:						
	— Other electric conductors, for a voltage not exceeding 80 V						
8544 41	— — Fitted with connectors						
8544 41 10	— — — Of a kind used for telecommunications	4,6	free	3,4	2,3	1,1	free
8544 41 90	— — — Other						
8544 49	— — Other						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
8544 49 20	– – – Of a kind used for telecommunications	4,8	free	3,6	2,4	1,2	free
8544 49 80	– – – Other						
	– Other electric conductors, for a voltage exceeding 80 volts but not exceeding 1 000 volts						
8544 51	– – Fitted with connectors						
8544 51 10	– – – Of a kind used for telecommunications	4,6	free	3,4	2,3	1,1	free
8544 51 90	– – – Other						
8544 70 00	– Optical fibre cables	6,3	free	4,7	3,1	1,6	free
8548	Waste and scrap of primary cells, primary batteries and electric accumulators; spent primary cells, spent primary batteries and spent electric accumulators; electrical parts of machinery or apparatus, not specified or included elsewhere in this chapter						
8548 10	– Waste and scrap of primary cells, primary batteries and electric accumulators; spent primary cells, spent primary batteries and spent electric accumulators						
8548 10 10	– – Spent primary cells, spent primary batteries						
	– – Spent electric accumulators						
8548 10 21	– – – Lead-acid accumulators						
8548 10 29	– – – Other						
	– – Waste and scrap of primary cells, primary batteries and electric accumulators						
8548 10 91	– – – Containing lead						
8548 10 99	– – – Other						
8548 90 00	– Other						
8548 90 10	– – Dynamic random-access memories (D-RAMs) in multi-combinational forms such as 'stack D-RAMs' and modules	3,3	free	2,5	1,6	0,8	free
8548 90 90	– – Other						
9006	Photographic (other than cinematographic) cameras; photographic flashlight apparatus and flashbulbs other than discharge lamps of heading No 8539:						
9006 10	– Cameras of a kind used for preparing printing plates or cylinders						
9006 10 10	– – Pattern generating apparatus of a kind used for producing masks or reticles from photoresist coated substrates	free	free	free	free	free	free
9006 10 90	– – Other						
	– Parts and accessories:						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
9006 91 00	— — For cameras						
	— — Other						
9006 99 10	— — — of apparatus of subheading 9006 10 10	4	free	3,0	2,0	1,0	free
9006 99 90	— — — Other						
9009	Photocopying apparatus incorporating an optical system or of the contact type and thermo-copying apparatus:						
	— Electrostatic photocopying apparatus						
9009 11 00	— — Operating by reproducing the original image directly onto the copy (direct process)	6,5	free	4,9	3,3	1,6	free
	— Other photocopying apparatus						
9009 21 00	— — Incorporating an optical system	6,5	free	4,9	3,3	1,6	free
9009 90	— Parts and accessories						
9009 90 10	— — Of electrostatic photocopying apparatus or other photocopying apparatus incorporating an optical system	6,5	free	4,9	3,3	1,6	free
9009 90 90	— — Other	3,8	free	2,8	1,9	0,9	free
9010	Apparatus and equipment for photographic (including cinematographic) laboratories (including apparatus for the projection of circuit patterns on sensitized semiconductor material), not specified or included elsewhere in this chapter, negatoscopes, projection screens						
	— Apparatus for the projection or drawing of circuit patterns on sensitized semiconductor materials:						
9010 41 00	— — Direct write-on-wafer apparatus	free	free	free	free	free	free
9010 42 00	— — Step and repeat aligners	free	free	free	free	free	free
9010 49 00	— — Other	free	free	free	free	free	free
	— — Other apparatus and equipment for photographic (including cinematographic) laboratories; negatoscopes						
9010 50 10	— — — Apparatus for the projection or drawing of circuit patterns on sensitized flat panel displays substrates	3,6	free	2,7	1,8	0,9	free
9010 50 90	— — — Other						
9010 90	— Parts and accessories						
9010 90 10	— — Of apparatus of subheading 9010 41 00, 9010 42 00, 9010 49 00 or 9010 50 10	3,6	free	2,7	1,8	0,9	free
9010 90 90	— — Other						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
9011	Compound optical microscopes, including those for photomicrography, cinephotomicrography or microprojection						
9011 10	– Stereoscopic microscopes						
9011 10 10	– – fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	8	free	6,0	4,0	2,0	free
9011 10 90	– – Other						
9011 20	– Other microscopes, for photomicrography, cinephotomicrography or micro-projection						
9011 20 10	– – fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	8	free	6,0	4,0	2,0	free
9011 20 90	– – Other						
9011 90	– Parts and accessories						
9011 90 10	– – Of apparatus of subheadings 9011 10 10 or 9011 20 10	8	free	6,0	4,0	2,0	free
9011 90 90	– – Other						
9012	Microscopes other than optical microscopes, diffraction microscopes						
9012 10	– Microscopes other than optical microscopes and diffraction apparatus						
9012 10 10	– – Electron beam microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	4,5	free	3,4	2,3	1,1	free
9012 10 90	– – Other						
9012 90	– Parts and accessories						
9012 90 10	– – Of apparatus of subheading 9012 10 00	4,5	free	3,4	2,3	1,1	free
9012 90 90	– – Other						
9013	Liquid crystal devices not constituting articles provided for more specifically in other headings; lasers, other than laser diodes; other optical appliances and instruments, not specified or included elsewhere in this chapter						
9013 80	– Other devices, appliances and instruments						
	– – Liquid crystal devices:						
	– – – Active matrix liquid crystal devices						
9013 80 11	– – – – Colour	6,5	free	4,9	3,3	1,6	free
9013 80 19	– – – – Black and white or other monochrome	6,5	free	4,9	3,3	1,6	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
9013 80 30	— — — Other	6,5	free	4,9	3,3	1,6	free
9013 80 90	— — Other						
9013 90	— Parts and accessories						
	— — Other						
9013 90 10	— — — For liquid crystal devices (LCD)	6,5	free	4,9	3,3	1,6	free
9013 90 90	— — — Other						
9017	Drawing, marking-out or mathematical calculating instruments (for example , drafting machines, pantographs, protractors, drawing sets, slide rules, disc calculators); instruments for measuring length, for use in the hand (for example, measuring rods and tapes, micrometers, callipers), not specified or included elsewhere in this chapter:						
9017 10	— Drafting tables and machines, whether or not automatic						
9017 10 10	— — Plotters	3,7	free	2,8	1,9	0,9	free
9017 10 90	— — Other						
9017 20	— Other drawing, marking-out or mathematical calculating instruments						
	— — Drawing instruments						
9017 20 05	— — — Plotters	3,7	free	2,8	1,9	0,9	free
9017 20 11	— — — Drawing sets						
9017 20 19	— — — Other						
	— — Marking-out instruments						
9017 20 31	— — — Pattern generating apparatus of a kind used for producing masks or reticles from photoresist coated substrates	free	free	free	free	free	free
9017 20 39	— — — Other						
9017 20 90	— — Mathematical calculating instruments (including slide rules, disc calculators and the like)						
9017 90	— Parts and accessories						
9017 90 10	— — For apparatus of subheading 9017 20 31	3,7	free	2,8	1,9	0,9	free
9017 90 90	— — Other						
9026	Instruments and apparatus for measuring or checking the flow, level, pressure or other variables of liquids or gases (for example, flow meters, level gauges, manometers, heat meters), excluding instruments and apparatus of heading Nos 9014, 9015, 9028 or 9032:						
9026 10	— For measuring or checking the flow or level of liquids						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
9026 10 10	– – For use in civil aircraft	free	free	free	free	free	free
	– – Other						
	– – – Electronic						
9026 10 51	– – – – Flow meters	4,8	free	3,6	2,4	1,2	free
9026 10 59	– – – – Other	4,8	free	3,6	2,4	1,2	free
	– – – Other						
9026 10 91	– – – – Flow meters	3,6	free	2,7	1,8	0,9	free
9026 10 99	– – – – Other	3,6	free	2,7	1,8	0,9	free
9026 20	– For measuring or checking pressure						
9026 20 10	– – For use in civil aircraft	free	free	free	free	free	free
	– – Other						
9026 20 30	– – – Electronic	4,8	free	3,6	2,4	1,2	free
	– – – Other						
	– – – – Spiral or metal diaphragm type pressure gauges						
9026 20 51	– – – – – Appliances for measuring and non-automatically regulating tyre pressure	3,3	free	2,5	1,6	0,8	free
9026 20 59	– – – – – Other	3,3	free	2,5	1,6	0,8	free
9026 20 90	– – – – Other	3,3	free	2,5	1,6	0,8	free
9026 80	– Other instruments or apparatus						
9026 80 10	– – For use in civil aircraft	free	free	free	free	free	free
	– – Other						
9026 80 91	– – – Electronic	4,8	free	3,6	2,4	1,2	free
9026 80 99	– – – Other	3,6	free	2,7	1,8	0,9	free
9026 90	– Parts and accessories						
9026 90 10	– – For use in civil aircraft	free	free	free	free	free	free
9026 90 90	– – Other	3,3	free	2,5	1,6	0,8	free
9027	Instruments and apparatus for physical or chemical analysis (for example, polarimeters, refractometers, spectrometers, gas or smoke analysis apparatus); instruments and apparatus for measuring or checking viscosity, porosity, expansion, surface tension or the like; instruments and apparatus for measuring or checking quantities of heat, sound or light (including exposure meters); microtomes:						
9027 20	– Chromatographs and electrophoresis instruments						

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
9027 20 10	— — Chromatographs	3,5	free	2,6	1,8	0,9	free
9027 20 90	— — Electrophoresis instruments	4,4	free	3,3	2,2	1,1	free
9027 30 00	— Spectrometers, spectrophotometers and spectrographs using optical radiations (UV, visible, IR)	3,5	free	2,6	1,8	0,9	free
9027 50 00	— Other instruments and apparatus using optical radiations (UV, visible, IR)	4,4	free	3,3	2,2	1,1	free
9027 80	— Other instruments and apparatus						
	— — Electronic						
9027 80 11	— — — pH meters, rH meters and other apparatus for measuring conductivity	4,4	free	3,3	2,2	1,1	free
9027 80 15	— — — Apparatus for performing measurements of the physical properties of semiconductor materials or associated insulating and conducting layers during the semiconductor wafer production process	free	free	free	free	free	free
9027 80 18	— — — Other	4,4	free	3,3	2,2	1,1	free
	— — Other						
9027 80 91	— — — Viscometers, porosimeters and expansion meters	4	free	3,0	2,0	1,0	free
9027 80 95	— — — Apparatus for performing measurements of the physical properties of semiconductor materials or associated insulating and conducting layers during the semiconductor wafer production process	free	free	free	free	free	free
9027 80 98	— — — Other	4	free	3,0	2,0	1,0	free
9027 90	— Microtomes; parts and accessories						
9027 90 10	— — Microtomes						
9027 90 50	— — Parts and accessories of apparatus of subheadings 9027 20 to 9027 80	4,4	free	3,3	2,2	1,1	free
9027 90 80	— — Parts and accessories of microtomes or of gas or smoke analysis apparatus						
9030	Oscilloscopes, spectrum analysers and other instruments and apparatus for measuring or checking electrical quantities, excluding meters of heading No 9028; instruments and apparatus for measuring or detecting alpha, beta, gamma, X-ray, cosmic or other ionizing radiations:						
9030 40	— Other instruments and apparatus, specially designed for telecommunications (for example, cross-talk meters, gain measuring instruments, distortion factor meters, psophometers)						
9030 40 10	— — For use in civil aircraft	free	free	free	free	free	free
9030 40 90	— — Other	5,5	free	4,1	2,8	1,4	free
	— Other instruments and apparatus						
9030 82 00	— — For measuring or checking semiconductor wafers or devices	free	free	free	free	free	free

CN 97	Label	Base rate	Final bound rate	Implementation			
				July 1997	1998	1999	2000
9030 90	— Parts and accessories						
9030 90 10	— — For use in civil aircraft	4,4	free	3,3	2,2	1,1	free
9030 90 20	— — For apparatus of subheading 9030 82 00						
9030 90 80	— — Other						
9031	Measuring or checking instruments, appliances and machines, not specified or included elsewhere in this chapter; profile projectors:						
	— Other optical instruments and appliances						
9031 41 00	— — For inspecting semiconductor wafers or devices or for inspecting photomasks or reticles used in manufacturing semiconductor devices	free	free	free	free	free	free
9031 49	— — Other						
9031 49 10	— — — For measuring surface particulate contamination on semiconductor wafers	free	free	free	free.	free	free
9031 49 90	— — — Other						
9031 90	— Parts and accessories						
9031 90 10	— — Of instruments, appliances and machines of subheading 9031 80, for use in civil aircraft	4,6	free	3,4	2,3	1,1	free
9031 90 20	— — For apparatus of subheadings 9031 41 00 and 9031 49 10						
9031 90 90	— — Other						

EC-ITA — Schedule CXL — Attachment A, Section 2

Description	HS 97 Headings
* Quartz reactor tubes and holders designed for insertion into diffusion and oxidation furnaces for production of semiconductor wafers	7020 00 05
* Chemical vapour deposition apparatus for semiconductor production	8419 89 20
* Parts of chemical vapour deposition apparatus for semiconductor production	8419 90 30
* Spin dryers for semiconductor wafer processing	8421 19 95
* Parts of spin dryers for semiconductor wafer processing	8421 91 10
* Deflash machines for cleaning and removing contaminants from the metal leads of semiconductor packages prior to the electroplating process	8424 89 30
* Spraying appliances for etching, stripping or cleaning semiconductor wafers	8424 89 20
* Parts of spraying appliances for etching, stripping or cleaning semiconductor wafers	8424 90 10
* Machines for working any material by removal of material, by laser or other light or photo beam in the production of semiconductor wafers	8456 10 10
* Apparatus for stripping or cleaning semiconductor wafers	8456 99 30
* Machines for dry-etching patterns on semiconductor materials	8456 91 00
* Focused ion beam milling machines to produce or repair masks and reticles for patterns on semiconductor devices	8456 99 10
* Lasercutters for cutting contacting tracks in semiconductor production by laser beam	8456 10 10
* Machines for sawing monocrystal semiconductor boules into slices, or wafers into chips	8464 10 10
* Grinding, polishing and lapping machines for processing of semiconductor wafers	8464 20 05
* Dicing machines for scribing or scoring semiconductor wafers	8464 90 10
* Parts for machines for sawing monocrystal semiconductor boules into slices, or wafers into chips	8466 91 15
* Parts of dicing machines for scribing or scoring semiconductor wafers	8466 91 15
* Parts of grinding, polishing and lapping machines for processing of semiconductor wafers	8466 91 15
* Parts of focused ion beam milling machines to produce or repair masks and reticles for patterns on semiconductor devices	8466 93 15
* Parts of lasercutters for cutting contacting tracks in semiconductor production by laser beam	8466 93 15
* Parts of machines for working any material by removal of material, by laser or other light or photo beam in the production of semiconductor wafers	8466 93 15
* Parts of apparatus for stripping or cleaning semiconductor wafers	8466 93 15
* Parts of machines for dry-etching patterns on semiconductor materials	8466 93 15
* Encapsulation equipment for assembly of semiconductors	8477 10 10 8477 59 05
* Parts of encapsulation equipment	8477 90 05
* Automated machines for transport, handling and storage of semiconductor wafers, wafer cassettes, wafer boxes and other material for semiconductor devices	8428 39 93
* Apparatus for growing or pulling monocrystal semiconductor boules	8479 89 65
* Apparatus for physical deposition by sputtering on semiconductor wafers	8419 89 25 8543 89 70

Description	HS 97 Headings
* Apparatus for wet etching, developing, stripping or cleaning semiconductor wafers and flat panel displays	8479 89 75 8479 89 76
* Die attach apparatus, tape automated bonders, and wire bonders for assembly of semiconductors	8479 89 77 8515 80 05 8515 90 10
* Encapsulation equipment for assembly of semiconductors	8479 89 79 8543 89 73
* Epitaxial deposition machines for semiconductor wafers	8479 89 70
* Machines for bending, folding and straightening semiconductor leads	8462 21 05 8462 29 05
* Physical deposition apparatus for semiconductor production	8543 89 72
* Spinners for coating photographic emulsions on semiconductor wafers	8421 19 93
* Part of apparatus for physical deposition by sputtering on semiconductor wafers	8543 90 30
* Parts for die attach apparatus, tape automated bonders, and wire bonders for assembly of semiconductors	8479 90 50
* Parts for spinners for coating photographic emulsions on semiconductor wafers	8421 91 10
* Parts of apparatus for growing or pulling monocrystal semiconductor boules	8479 90 50
* Parts of apparatus for wet etching, developing, stripping or cleaning semiconductor wafers and flat panel displays	8479 90 50 8543 90 30
* Parts of automated machines for transport, handling and storage of semiconductor wafers, wafer cassettes, wafer boxes and other material for semiconductor devices	8431 39 20
* Parts of encapsulation equipment for assembly of semiconductors	8479 90 50 8543 90 30
* Parts of epitaxial deposition machines for semiconductor wafers	8479 90 50
* Parts of machines for bending, folding and straightening semiconductor leads	8466 94 10
* Parts of physical deposition apparatus for semiconductor production	8419 90 30 8543 90 30
* Injection and compression moulds for the manufacture of semiconductor devices	8480 71 10
* Resistance heated furnaces and ovens for the manufacture of semiconductor devices on semiconductor wafers	8514 10 05 8514 30 11 8514 30 91
* Inductance or dielectric furnaces and ovens for the manufacture of semiconductor devices on semiconductor wafers	8514 20 05
* Apparatus for rapid heating of semiconductor wafers	8419 89 15 8514 30 91
* Parts of resistance heated furnaces and ovens for the manufacture of semiconductor devices on semiconductor wafers	8514 90 10
* Parts of apparatus for rapid heating of wafers	8419 90 30 8514 90 10
* Parts of furnaces and ovens of headings No 8514 10 to No 8514 30	8514 90 10
* Wafer probers	8536 90 20
* Ion implanters for doping semiconductor materials	8543 11 00
* Apparatus for wet etching, developing, stripping or cleaning semiconductor wafers and flat panel displays	8479 89 75 8479 89 76 8543 30 10 8543 30 20

Description	HS 97 Headings
* Parts of apparatus for wet etching, developing, stripping or cleaning semiconductor wafers and flat panel displays	8479 90 50 8543 90 30
* Parts of ion implanters for doping semiconductor materials	8543 90 30
* Apparatus for projection, drawing or plating circuit patterns on sensitized semiconductor materials and flat panel displays	9010 41 00 9010 42 00 9010 49 00 9010 50 10
* Parts and accessories of the apparatus of headings No 9010 41 to 9010 49	9010 90 10
* Optical stereoscopic microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	9011 10 10
* Photomicrographic microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	9011 20 10
* Parts and accessories of optical stereoscopic microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	9011 90 10
* Parts and accessories of photomicrographic microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	9011 90 10
* Electron beam microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	9012 10 10
* Parts and accessories of electron beam microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	9012 90 10
* Pattern generating apparatus of a kind used for producing masks or reticles from photoresist coated substrates	9006 10 10 9017 20 31
* Parts and accessories for pattern generating apparatus of a kind used for producing masks or reticles from photoresist coated substrates	9006 99 10 9017 90 10
* Parts of such pattern generating apparatus	9017 90 10
* Instruments and apparatus for measuring or checking semiconductor wafers or devices	9030 82 00
* Parts and accessories of instruments and apparatus for measuring or checking semiconductor wafers or devices	9030 90 20
* Parts of instruments and appliances for measuring or checking semiconductor wafers or devices	9030 90 20
* Optical instruments and appliances for inspecting semiconductor wafers or devices or for inspecting masks, photomasks or reticles used in manufacturing semiconductor devices	9031 41 00
* Optical instruments and appliances for measuring surface particulate contamination on semiconductor wafers	9031 49 10
* Parts and accessories of optical instruments and appliances for inspecting semiconductor wafers or devices or for inspecting masks, photomasks or reticles used in manufacturing semiconductor devices	9031 90 20
* Parts and accessories of optical instruments and appliances for measuring surface particulate contamination on semiconductor wafers	9031 90 20

EC-ITA — Schedule CXL — Attachment B

Description	HS 97 Headings
* Computers: automatic data processing machines capable of (1) storing the processing program or programs and at least the data immediately necessary for the execution of the program; (2) being freely programmed in accordance with the requirements of the user; (3) performing arithmetical computations specified by the user; (4) executing without human intervention, a processing program which requires them to modify their execution, by logical decision during the processing run. The agreement covers automatic data processing machines whether or not they are able to receive and process with assistance of central processing unit telephony signals, television signals, or other analogue or digitally processed audio or video signals. Machines performing a specific function other than data processing, or incorporating or working in conjunction with an automatic data processing machine, and not otherwise specified under Attachment A or B, are not covered by this agreement. The agreement covers such automatic data processing machines whether or not they are able to receive and process with the assistance of the central processing unit telephony signals, television signals, or other analogue or digitally processed audio or video signals. However, machines performing a specific function other than data processing, or incorporating or working in conjunction with an automatic data processing machine, and not referred to under part A or B, are excluded from the product coverage of this agreement.	8741 10 90 8471 30 00 8471 41 90 8471 49 90 8471 50 90 8528 12 10 8528 13 10 8543 89 17
* Electric amplifiers when used as repeaters in line telephony products falling within this agreement, and parts thereof.	8517 50 10 8517 80 90
* Flat panel display devices (including LCD, electro-luminescence, plasma, vacuum-fluorescence and other technologies) for products falling within this agreement, and parts thereof.	8471 60 90 8473 30 10 8473 30 90 8531 20 30 8531 20 51 8531 20 59 8531 20 80 8531 80 30 8531 90 10 8531 90 30 9013 80 11 9013 80 19 9013 80 30 9013 90 10
* Network equipment: local area network (LAN) and wide area network (WAN) apparatus, including those products dedicated for use solely or principally to permit the interconnection of automatic data processing machines and units thereof for a network that is used primarily for the sharing of resources such as central processor units, data storage devices and input or output units — including adapters, hubs, in-line repeaters, converters, concentrators, bridges and routers, and printed circuit assemblies for physical incorporation into automatic data processing machines and units thereof.	8471 50 90 8471 60 90 8517 50 90
* Monitors: display units of automatic data processing machines with a cathode ray tube with a dot screen pitch smaller than 0,4 mm not capable of receiving and processing television signals or other analogue or digitally processed audio or video signals without assistance of a central processing unit of a computer as defined in this agreement. The agreement does not, therefore, cover televisions, including high definition televisions (1).	8471 60 90
* Optical disc storage units for automatic data processing machines (including CD drives and DVD-drives), whether or not having the capability of writing/recording as well as reading, whether or not in their own housings.	8471 70 51

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(1) Participants will conduct a review of this product description in January 1999 under the consultation of paragraph 3 of the Declaration.

Description	HS 97 Headings
* Paging alert devices and parts thereof.	8527 90 92 8529 90 40
* Plotters whether input or output units of HS heading No 8471 or drawing or drafting machines of HS heading No 9017.	8471 60 90 8471 80 90 9017 10 10 9017 20 05
* Printed circuit assemblies for products falling within this agreement, including such assemblies for external connections such as cards that conform to the PCMCIA standard. Such printed circuit assemblies consist of one or more printed circuits of heading 8534 with one or more active elements assembled thereon, with or without passive elements 'Active elements' means diodes, transistors and similar semiconductor devices, whether or not photosensitive, of heading 8541, and integrated circuits and micro assemblies of heading 8542.	8473 10 11 8473 21 10 8473 29 10 8473 30 10 8473 40 11 8473 50 10 8504 90 05 8504 90 91 8517 80 90 8517 90 11 8517 90 82 8522 90 51 8528 12 90 8529 90 40 8531 90 10 8531 90 30 8543 90 20 8543 90 30 8548 90 10 9026 90 90 9027 90 50 9030 90 20
* Projection type flat panel display units used with automatic data processing machines which can display digital information generated by the central processing unit.	8471 60 90 8528 30 05 8531 80 30
* Proprietary format storage devices including media therefor for automatic data processing machines, with or without removable media and whether magnetic, optical or other technology, including Bernoulli Box, Syquest, Zipdrive cartridge storage units.	8471 70 51 8471 70 53 8471 70 59 8471 70 60 8471 70 90 8523 20 11 8523 20 19 8523 20 90 8523 90 00 8524 31 00 8524 39 10 8524 40 10 8524 40 91 8524 40 99 8524 91 10 8524 91 90 8524 99 10
* Multimedia upgrade kits for automatic data processing machines, and units thereof, put up for retail sale, consisting of, at least, speakers and/or microphones, as well as a printed circuit assembly that enables the ADP machine and units thereof to process audio signals (sound cards).	8543 89 79
* Set top boxes which have communication function a microprocessor-based device incorporating a modem for gaining access to the internet, and having a function of interactive information exchange.	8517 50 90 8517 80 90 8525 20 99

WORLD TRADE ORGANIZATION

2 April 1997

Council for Trade in Goods

IMPLEMENTATION OF THE MINISTERIAL DECLARATION ON TRADE IN INFORMATION TECHNOLOGY PRODUCTS

The following communication was sent on 26 March 1997 to the Chairman of the Council for Trade in Goods with a request that it be circulated to all Members.

The following Members of the World Trade Organization ('WTO') and States or separate customs territories in the process of acceding to the WTO:

Australia
Canada
Czech Republic
Costa Rica
Estonia
European Communities
Hong Kong
Iceland
India
Indonesia
Israel
Japan
Korea
Macau
Malaysia
New Zealand
Norway
Romania
Separate Customs Territory of Taiwan, Penghu, Kinmen and Matsu
Singapore
Slovak Republic
Switzerland (1)
Thailand
Turkey
United States

(hereinafter referred to as 'participants') (2), having been parties to the Ministerial Declaration on Trade in Information Technology Products (3) (hereinafter referred to as 'Declaration'), or having agreed, in the period since the Declaration was circulated, to participate in the expansion of world trade in information technology products according to the modalities set forth in the Declaration, met on 26 March 1997 (4), took the decisions described below, as provided for in the Annex to the Declaration, and established the elements described below, concerning the further implementation of the Declaration, as reflected below.

Agreement on actions foreseen in the Declaration

1. The participants accepted (5) the results of the review process described in paragraph 2 of the Annex to the Declaration, as reflected in the documents attached hereto, which were submitted by participants and have been reviewed and approved on a consensus basis.

2. The participants agreed that the criteria established in paragraph 4 of the Annex to the Declaration have been met, and therefore, that participants shall implement (5) the actions foreseen in the Declaration.

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(1) On behalf of the customs union Switzerland and Liechtenstein.

(2) Participants took note that Panama and Poland submitted documents after 1 March 1997 that could not be reviewed by 26 March 1997 and that others may submit documents on or before 1 April 1997. Participants agreed to meet again during the week of 14 April 1997 to complete the review process with respect to these documents. It was understood that, upon approval of these documents, the procedures set forth in the Annex to the Declaration would apply as if the documents had been approved at the meeting of 26 March 1997, and the States or separate customs territories referred to above would thenceforth be considered to be 'participants' for purposes of the further implementation of the Declaration.

(3) WT/MIN(96)/16, 13 December 1996 (attached).

(4) The WTO Secretariat shall maintain a set of the informal documents exchanged by participants in consultations that led to the decisions taken at that meeting. These documents shall be made available to participants for consultation upon request.

(5) Subject to the completion of domestic procedural requirements.

Establishment of the Committee of Participants

3. In order to carry out the provisions of paragraphs 3, 5, 6 and 7 of the Annex to the Declaration, the participants established a Committee of Participants on the Expansion of Trade in Information Technology Products (hereinafter referred to as 'Committee'). The Committee shall oversee the functioning of these elements and shall serve as the forum for meetings required under its procedures and collective consultations among the participants. All decisions of the Committee shall be taken by consensus.

4. Membership in the Committee shall be open to representatives of all participants. The Committee shall elect a chairperson from among the representatives of the participants or as otherwise decided. The Committee may decide to invite, as appropriate, representatives of WTO Members and of observers to the Council for Trade in Goods that are not participants as of 26 March 1997 to attend meetings of the Committee as observers.

5. The participants agreed that any WTO Member, or State or separate customs territory in the process of acceding to the WTO, that is not a participant as of 26 March 1997, and that notifies the Committee of its interest in binding and eliminating customs duties, and other duties and charges, on the importation of information technology products into its territory pursuant to these elements, may become a participant on terms to be agreed between it and the participants at that time. Unless otherwise agreed, such WTO Member, or separate customs territory in the process of acceding to the WTO, shall, on the date that it becomes a participant, make effective all rate reductions it would have undertaken had it been a participant as of 26 March 1997.

6. The participants agreed that the Committee shall hold regular meetings to review developments related to the implementation of the Declaration, and shall hold special meetings at the request of any participant or as otherwise necessary by invitation of the chairperson. The first regular meeting of the Committee shall be held no later than 30 September 1997. The Committee shall consider at that meeting the schedule of future regular meetings, taking account of the meetings provided for in paragraph 7 below.

Process for monitoring implementation and consultations on and review of product coverage

7. The participants agreed that, in conducting the consultations and review described in paragraph 3 of the Annex to the Declaration (1), the Committee may also take into account changes in patterns in trade in information technology products. The participants expressed their intent to conduct the initial review and any consultations pursuant to paragraph 3 of the Annex to the Declaration according to the procedures attached hereto.

8. The participants also agreed that, in conducting the consultations described in paragraph 5 of the Annex to the Declaration (2), the Committee may consider product classification divergences with a view to ensuring that the actions foreseen in the Declaration are implemented in a coherent fashion by all participants.

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(1) The text of paragraph 3 is as follows: 'Participants shall meet periodically under the auspices of the Council on Trade in Goods to review the product coverage specified in the Attachments, with a view to agreeing, by consensus, whether in the light of technological developments, experience in applying the tariff concessions, or changes to the HS nomenclature, the Attachments should be modified to incorporate additional products, and to consult on non-tariff barriers to trade in information technology products. Such consultations shall be without prejudice to rights and obligations under the WTO Agreement.'

(2) The text of paragraph 5 is as follows: 'Participants shall meet as often as necessary and no later than 30 September 1997 to consider any divergence among them in classifying information technology products, beginning with the products specified in Attachment B. Participants agree on the common objective of achieving, where appropriate, a common classification for these products within existing HS nomenclature, giving consideration to interpretations and rulings of the Customs Cooperation Council (also known as the World Customs Organization or 'WCO'). In any instance in which a divergence in classification remains, participants will consider whether a joint suggestion could be made to the WCO with regard to updating existing HS nomenclature or resolving divergence in interpretation of the HS nomenclature.'

GATT 1994 Article XXVIII

9. The participants agreed that any participant that is a WTO Member having recourse to the provisions of Article XXVIII of the GATT 1994 with respect to the possible modification or withdrawal of a concession included in its WTO schedule of tariff concessions, as modified pursuant to these procedures, shall so notify the other participants at the time that it notifies the Director-General of the WTO. Upon the request of any participant, the Committee shall convene a meeting within 30 days of the circulation of the notification to consider the potential impact of the proposed modification or withdrawal of the concession on the trade of other participants in information technology products. Such deliberations shall be without prejudice to rights and obligations under the WTO Agreement.

10. The participants agreed that, in light of the technical specificity of information technology products, participants may wish to consider, in the course of the review provided for in paragraph 3 of the Annex to the Declaration, additional procedures to address the concerns of small- and medium-sized exporting participants regarding their rights under Article XXVIII, bearing in mind that a review will be conducted by the Council for Trade in Goods five years from the date of entry into force of the WTO Agreement pursuant to paragraph 1 of the Understanding on the Interpretation of Article XXVIII of the General Agreement on Tariffs and Trade 1994.

Incorporation of the Annex to the Declaration

11. The participants agreed that the modalities set forth in the Annex to the Declaration, including the Attachments to that Annex, are an integral part of these elements.

Attachments:

A. Ministerial Declaration on Trade in Information Technology Products, WT/MIN(96)/16, 13 December 1996.

B. Approved Schedules of Participants (1).

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(1) Available for consultation by participants and WTO Members in the WTO Secretariat (Market Access Division).

PROCEDURES FOR CONSULTATIONS ON AND REVIEW OF PRODUCT COVERAGE

Pursuant to paragraph 7 above, it is the intention of the participants to conduct the initial review and any consultations pursuant to paragraph 3 of the Annex to the Declaration according to the following schedule:

(a) Beginning 1 October 1997 and no later than 31 December 1997, participants may submit to the Committee lists of additional information technology products for possible additional tariff concessions, including supporting technical documentation to facilitate consideration by the Committee, taking into account paragraph 5 of the Annex to the Declaration regarding classification issues. Such lists shall be circulated to all participants.

(b) Beginning 1 January 1998 and no later than 31 March 1998, participants that have submitted the documentation described in paragraph (a) above shall consult upon request with interested participants to clarify information and exchange views on the documentation submitted, including technical specifications of the products covered in such documentation.

(c) No later than 30 June 1998, the Committee shall meet to decide whether to revise Attachment A or B to the Annex to the Declaration, and if so, to establish a revised list of products with respect to which participants would bind and eliminate customs duties and other duties and charges. Such list would replace Attachment A or B.

(d) If the Committee decides to establish a revised list pursuant to paragraph (c), then each participant shall submit no later than 1 September 1998 a document similar to that required under paragraph 2 of the Annex to the Declaration.

(e) The Committee shall meet no later than 15 September 1998 to conduct a review of these documents in a manner similar to that conducted pursuant to paragraph 2 of the Annex to the Declaration, and shall conclude its review no later than 30 September 1998. At that meeting participants shall also consider the possibility and procedures for further reviews.

(f) Upon successful completion of the Committee review, the participants shall submit to the Secretariat the documents incorporating the results of the review as proposed modifications to their WTO schedules of tariff concessions, pursuant to the Decision of 26 March 1980 on Procedures for Modification and Rectification of Schedules of Tariff Concessions (BISD, 27S/25), with a view to the entry into force of the revised schedules, and incorporation in their domestic tariff schedules, no later than 1 January 1999 bearing in mind the need of each participant to fulfil its domestic procedural requirements. Each participant that is not a Member of the WTO shall implement these measures on an autonomous basis, pending completion of its WTO accession, and shall incorporate these measures into its WTO schedule on goods.